

CABLINE®-VS IIF

フルシールド、多点GND接地&メカニカルロック付き、0.5mmピッチ、水平嵌合タイプFPCプラグコネクタ

Product Specifications:

Mating type	Horizontal	
Board Pitch (mm)	0.5	
Wiping Length (mm)	0.48	
Mated size (mm)	Height	1.2 max. with cover
	Width	Formula: 6.85 + (0.5*?p)
	Depth	7.24
Pin Counts	Range	Up to 55
	Available	30, 40

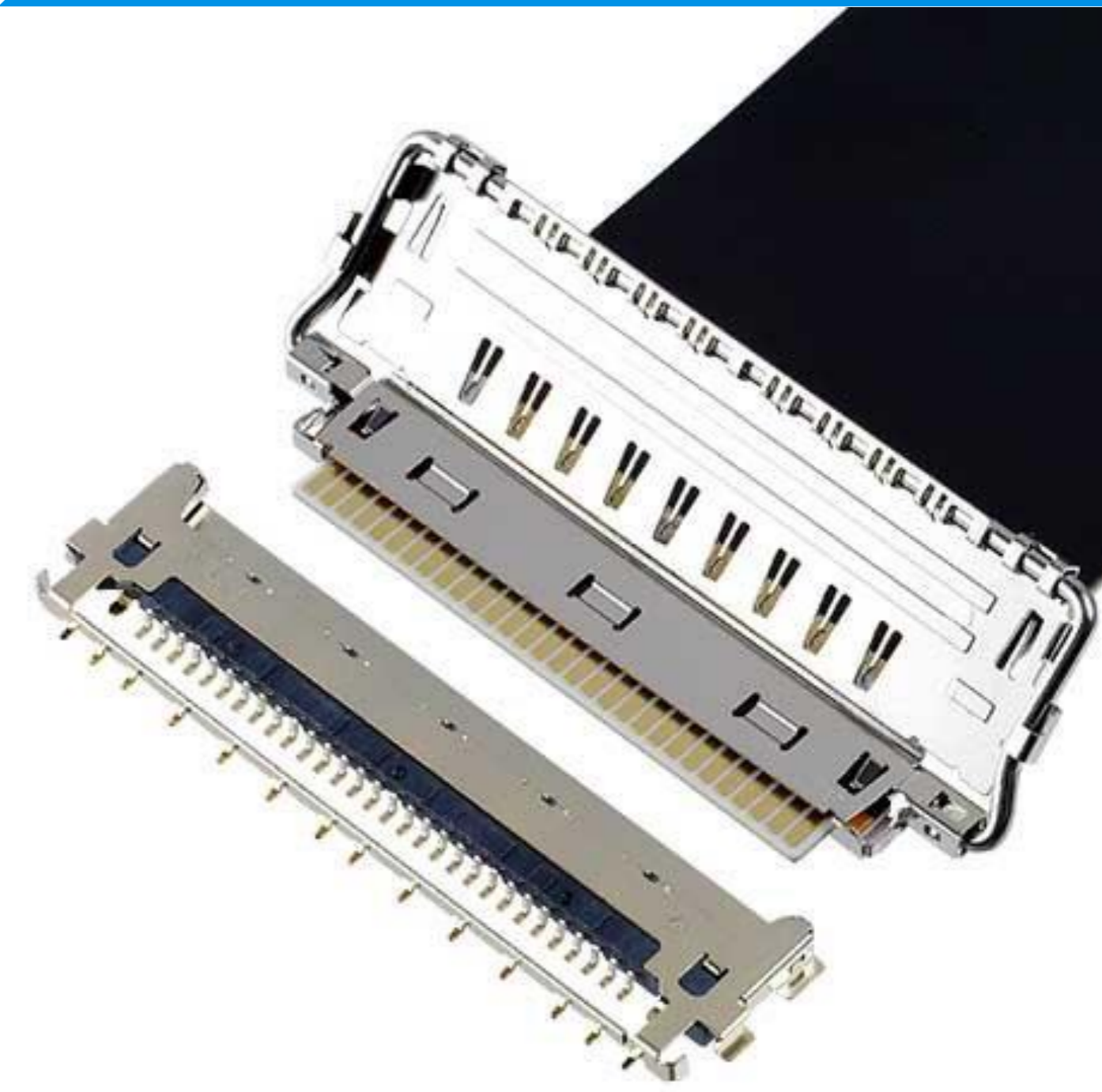
Applicable FPC

FPC Type	Shielded FPC
FPC Pitch (mm)	0.5
FPC Contact Point	Top
FPC Thickness (mm)	Contact Area: 0.25 +0.02/-0.03
	Ground Area: 0.37 +0.04/-0.06

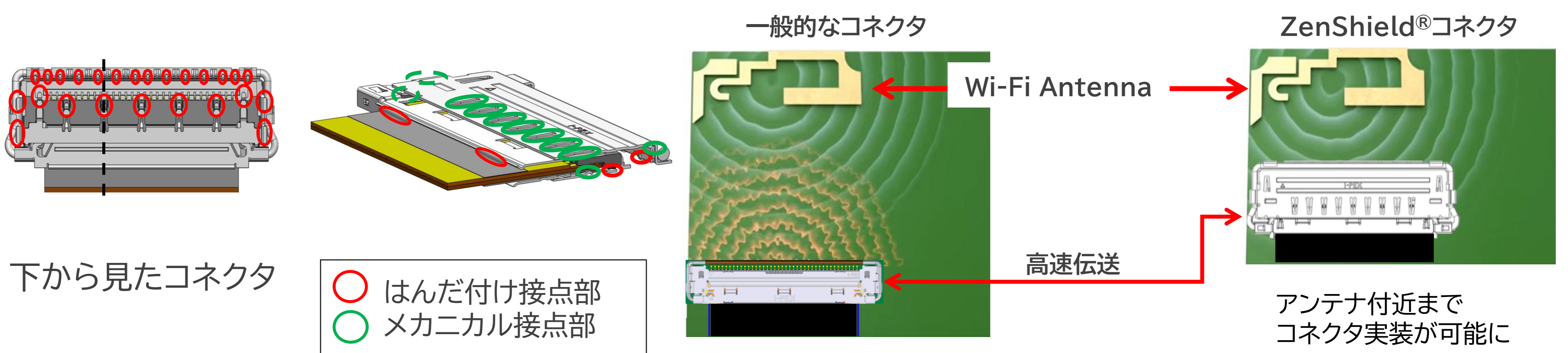
Applicable Standards (Reference Only):

USB4 Gen3 (20 Gbps/Lane), Display Port UHBR20 (20 Gbps/Lane)
PCIe® Gen 4 (16 GT/s/Lane), eDP HBR 3 (8.1 Gbps/Lane)

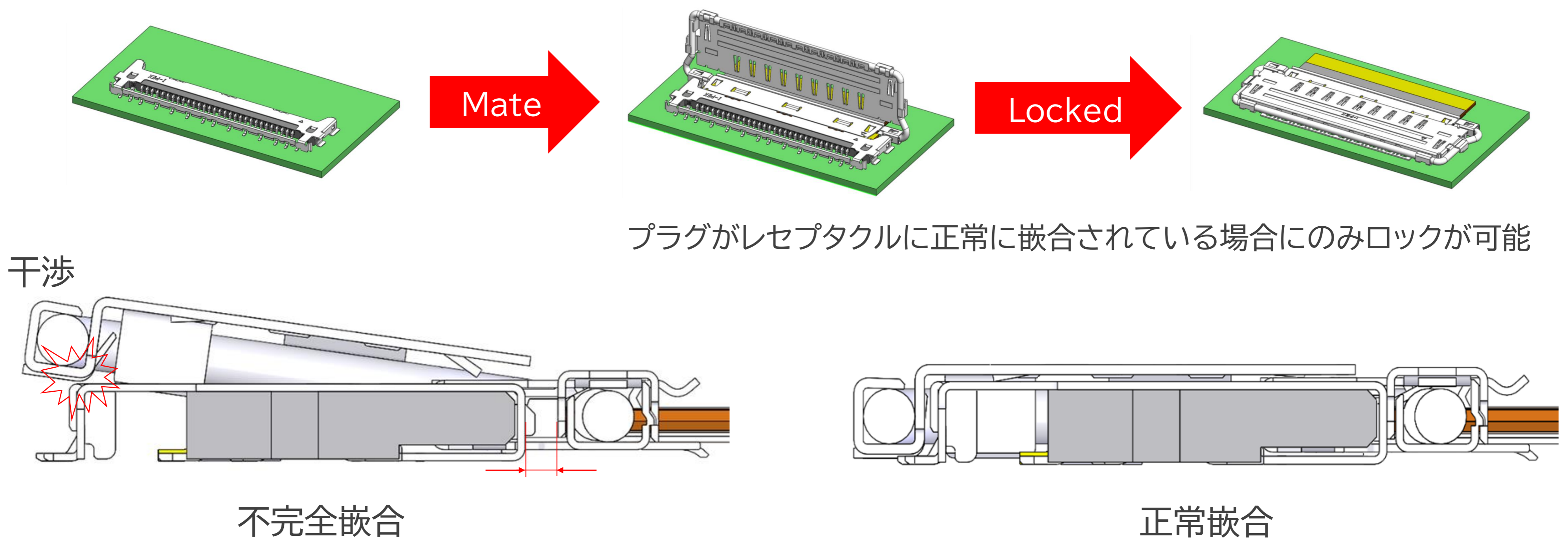
*記載のない極数の対応状況についてはお問い合わせください。



▶ ZenShield® フルシールドと多点グラウンド構造でEMI対策強化



▶ メカニカルロックバーによる半嵌合防止とプラグ抜け防止

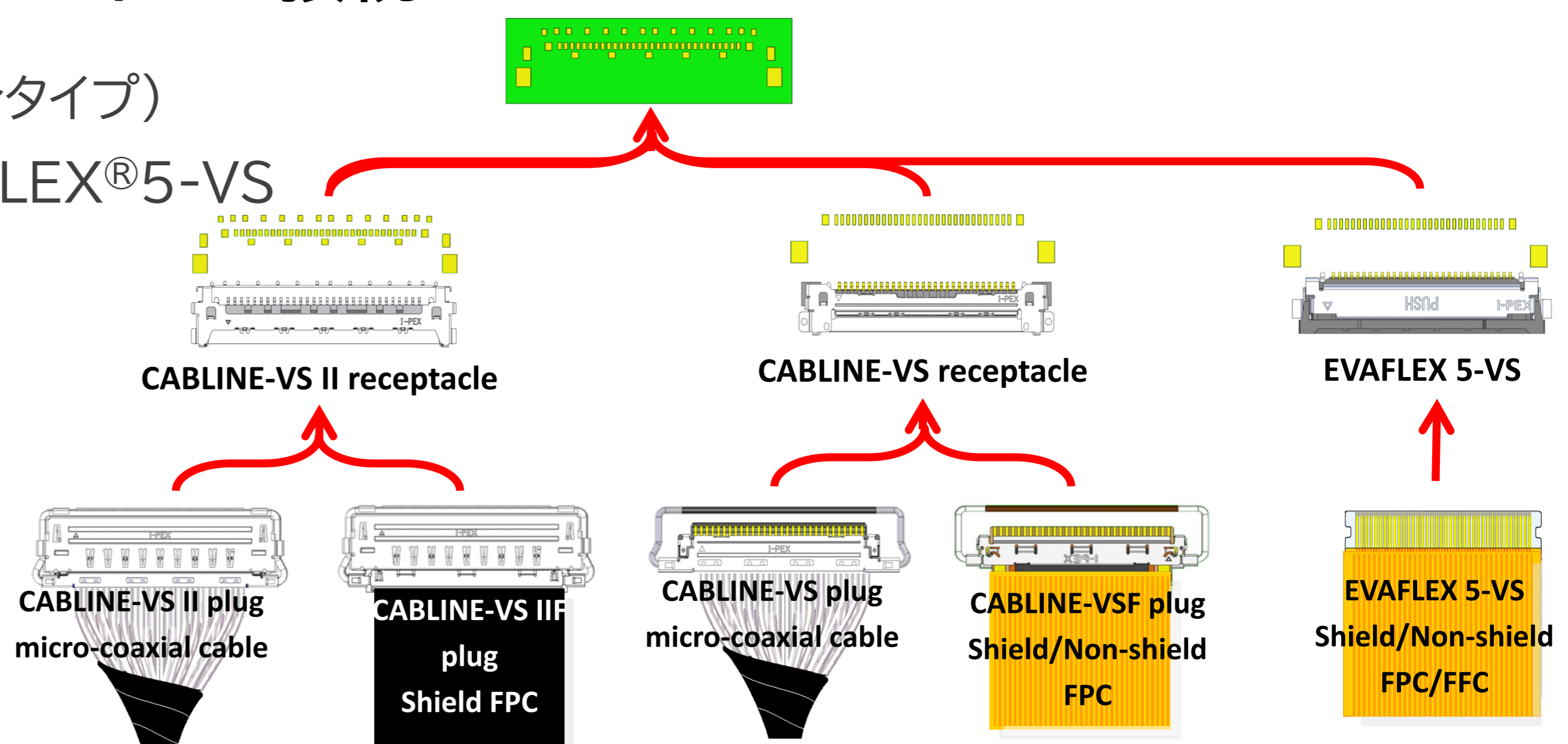


▶ I-PEX VSシリーズにおける複数のコネクタ接続オプション

I-PEX VSシリーズ (0.5mmピッチ、水平嵌合タイプ)

CABLINE-VS、VS II レセプタクル と EVAFLEX®5-VS は同じPCBレイアウトに実装可能

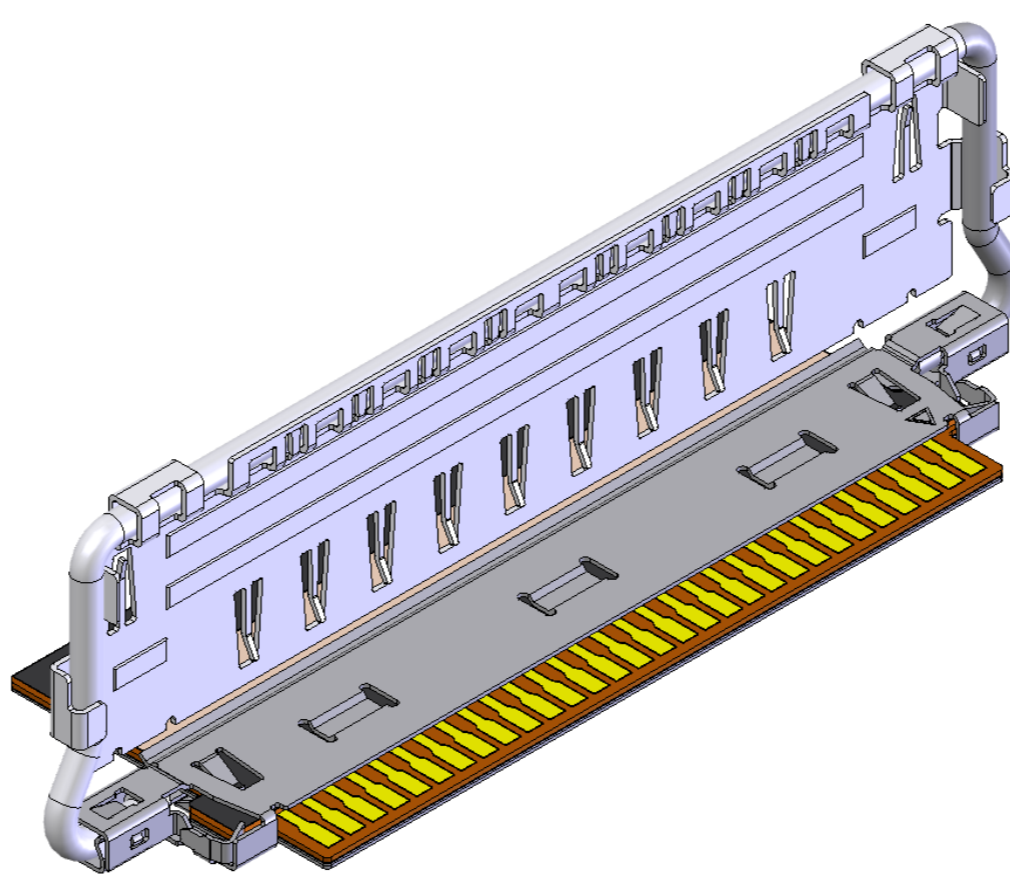
CABLINE-VS レセプタクル: VESA規格の標準コネクタとして、ノートPC パネル市場のシェア No.1を獲得



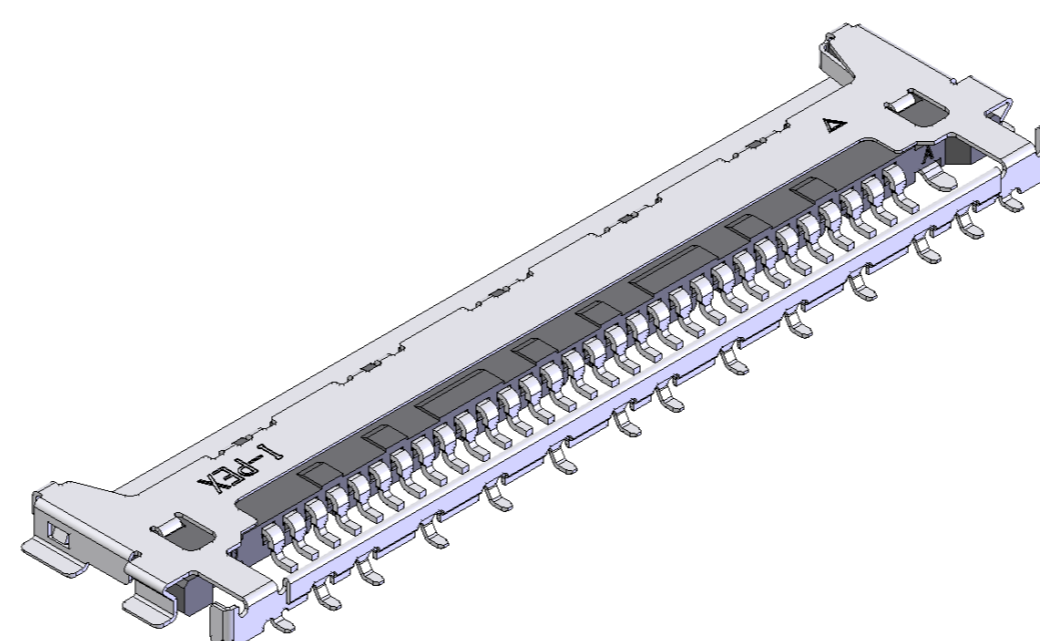
Component Parts Details

Component Parts

Connector parts



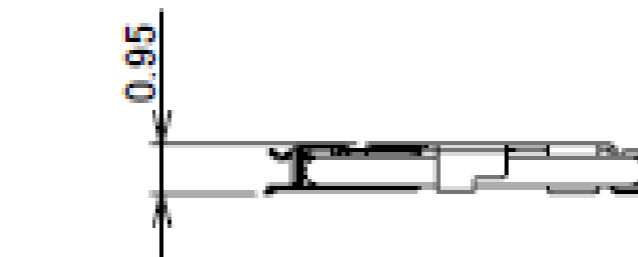
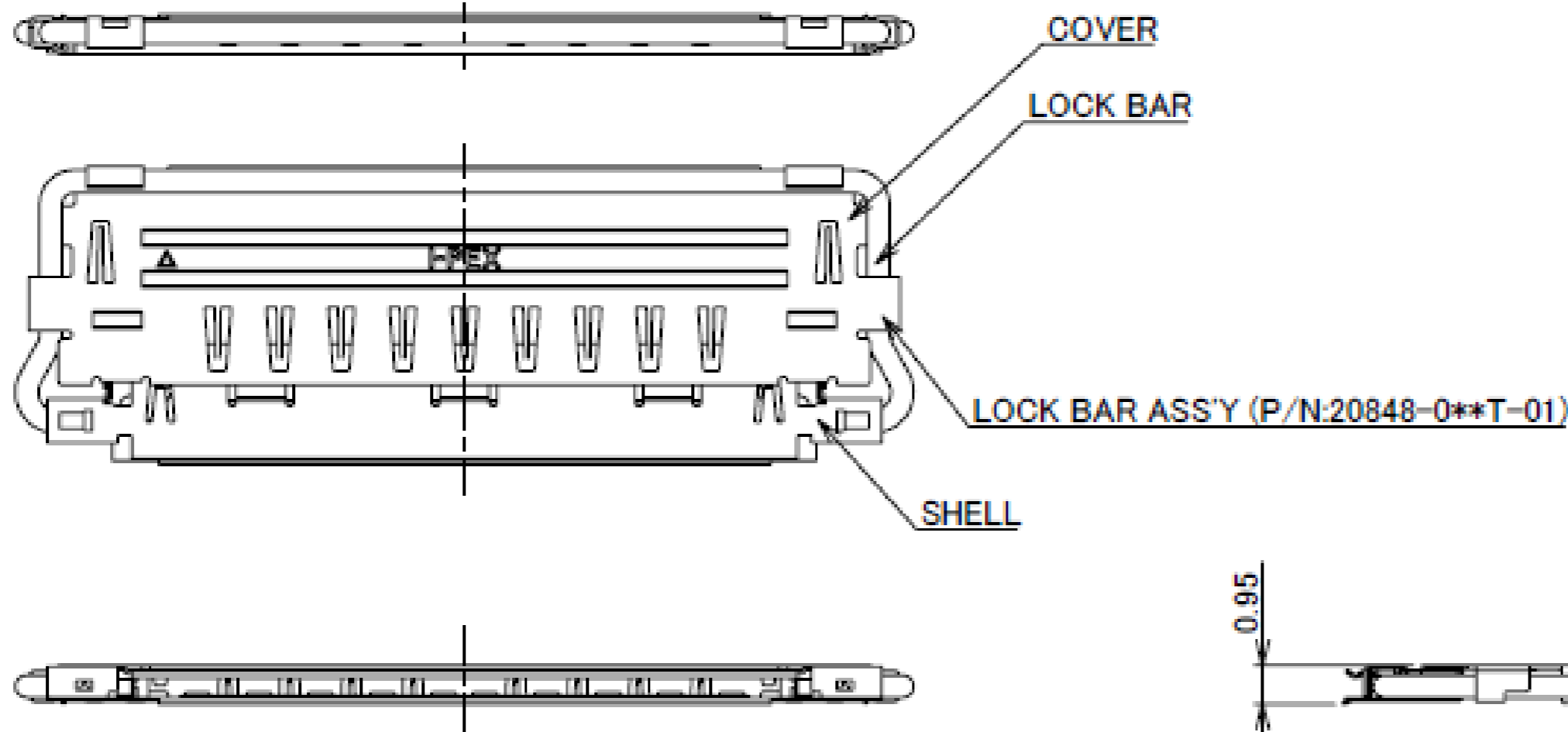
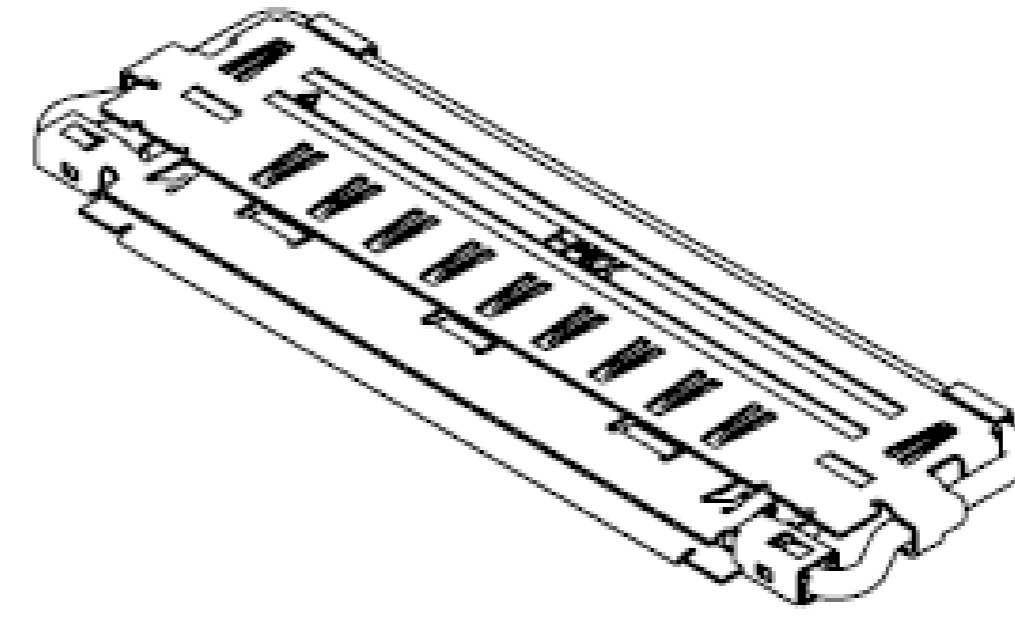
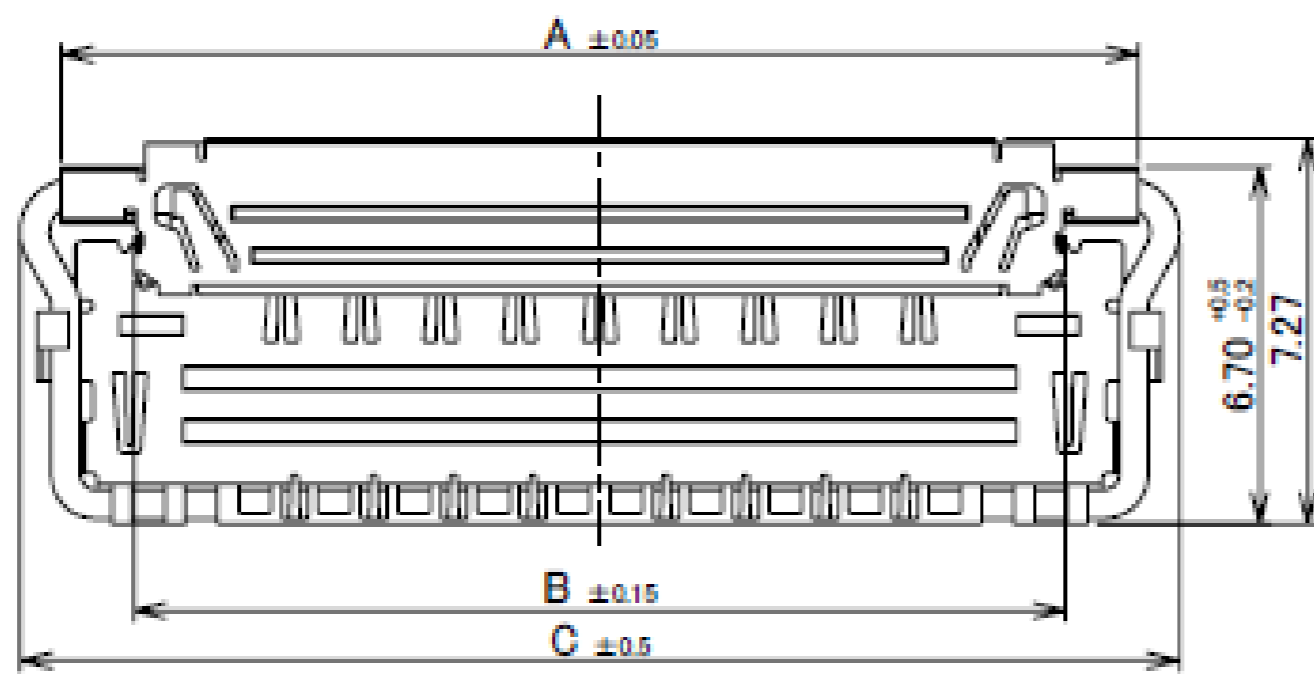
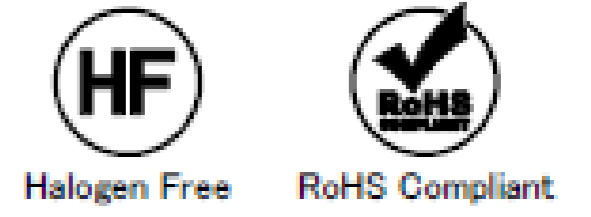
CABLINE-VS IIF PLUG with FPC



CABLINE-VS II RECEPTACLE

Shell Assembly

Recommended P/N		20862-0**T-01		
PART No.	Pos.	A	B	C
20862-030T-01	30	20.30	17.56	21.85
20862-040T-01	40	25.30	22.56	26.85

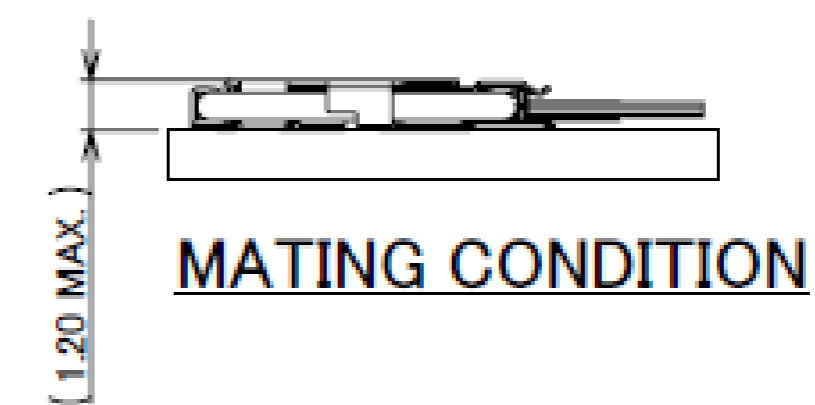
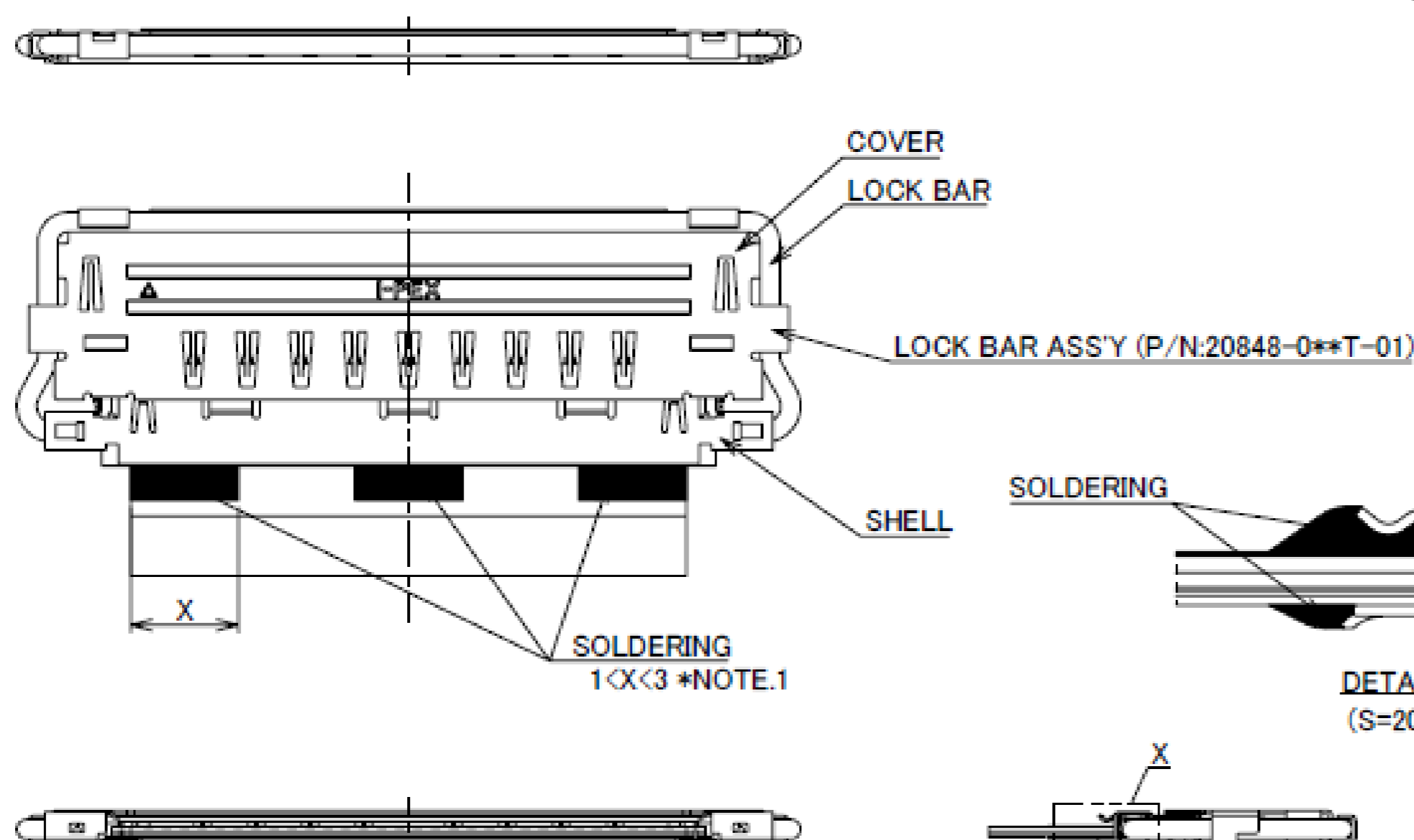
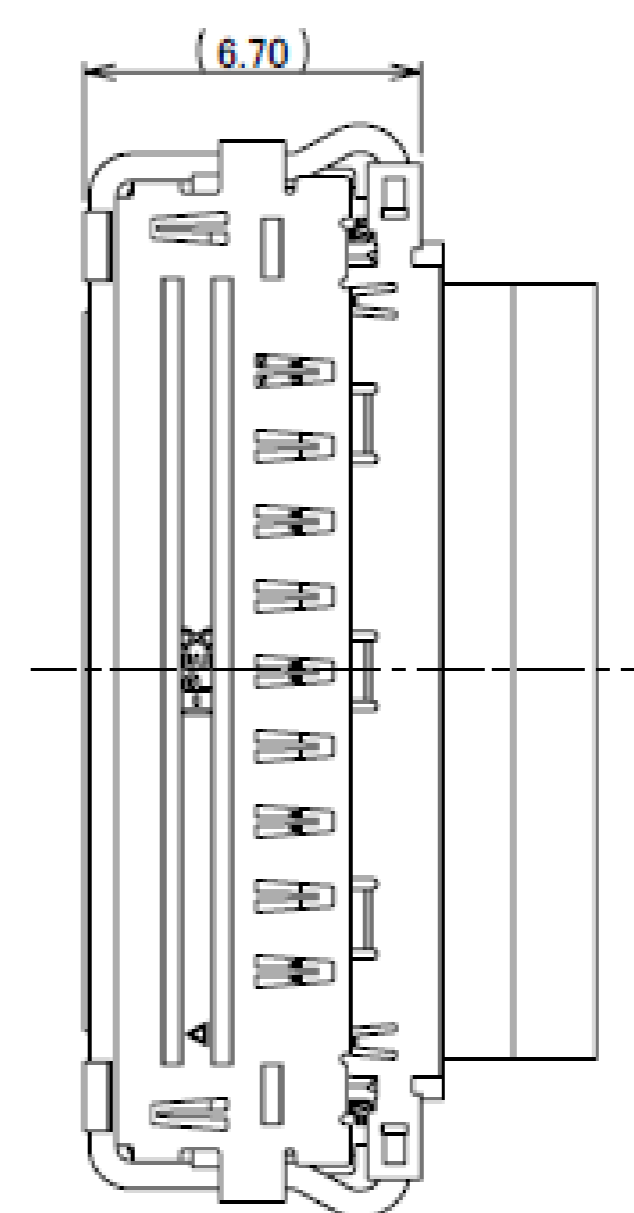
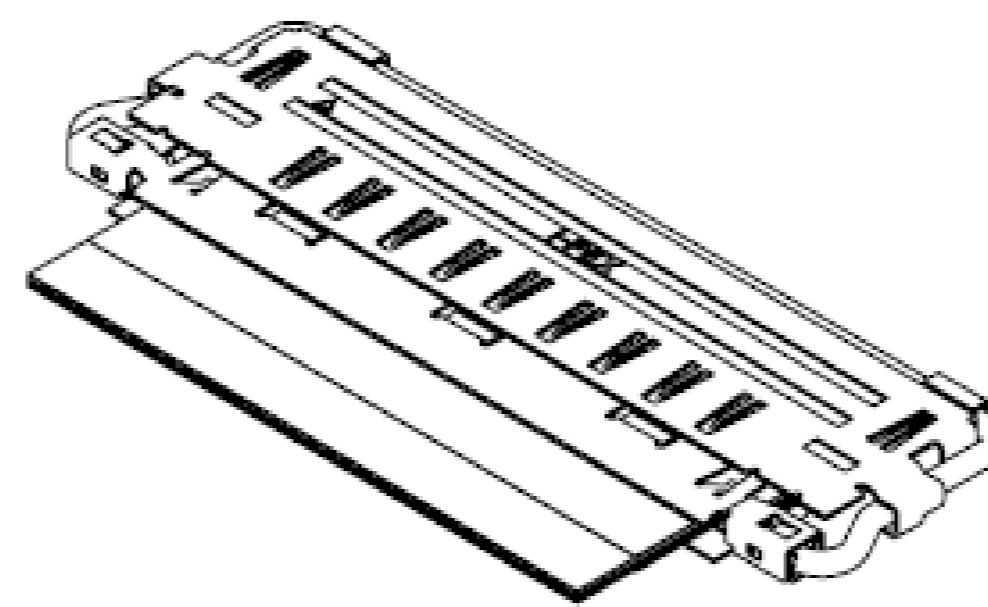
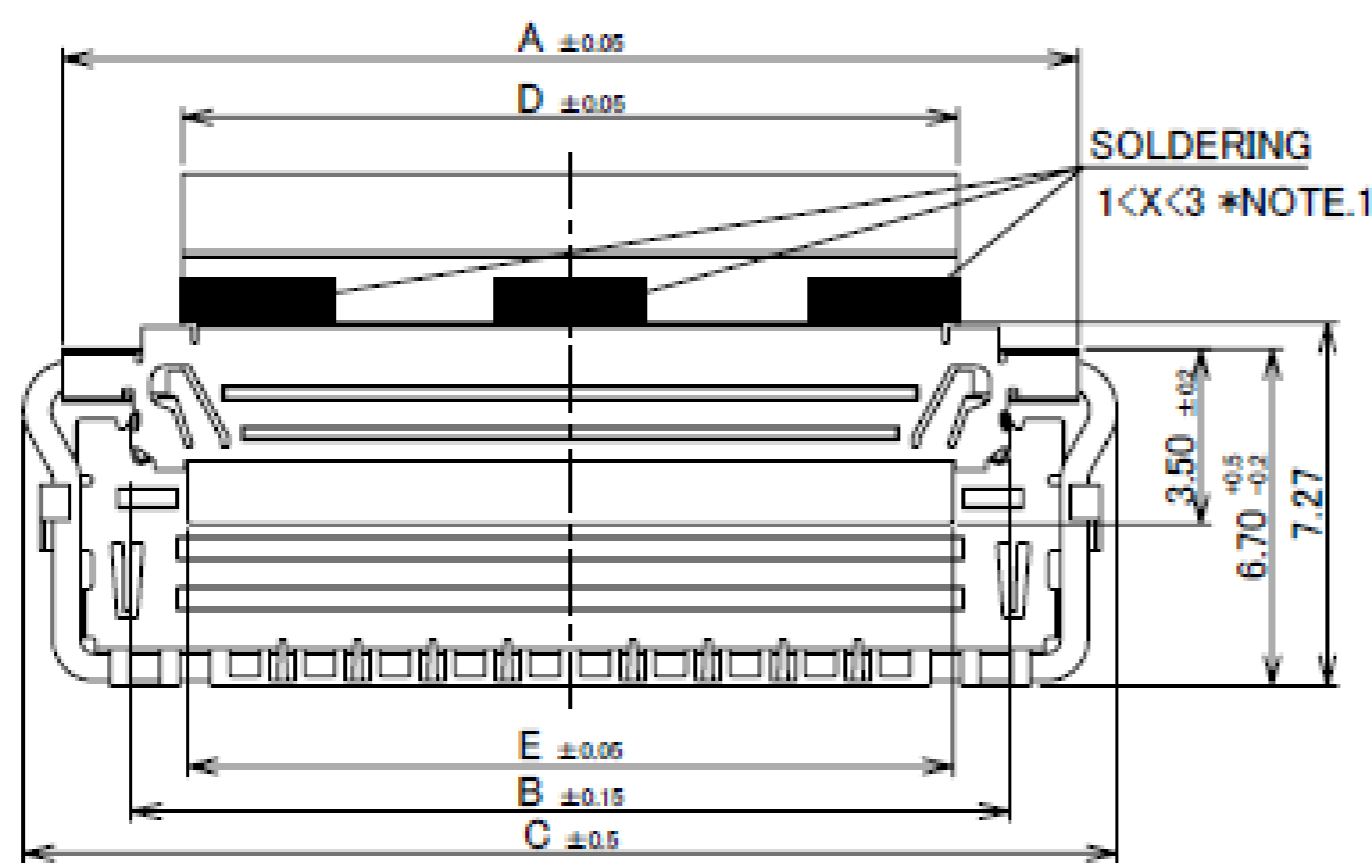


NO.	DISCRIPTION	MATERIAL	FINISH , REMARKS
3	COVER	PHOSPHOR BRONZE	Ni 1.00 μm MIN.
2	LOCK BAR	STAINLESS STEEL	-
1	SHELL	PHOSPHOR BRONZE	PARTIAL Au 0.003 μm MIN. OVER Ni 1.00 μm MIN.

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Recommended P/N		20862-0**T-01				
PART No.	Pos.	A	B	C	D	E
20862-030T-01	30	20.30	17.56	21.85	15.50	15.30
20862-040T-01	40	25.30	22.56	26.85	20.50	20.30

FPC ASS'Y STATE COVER CLOSE



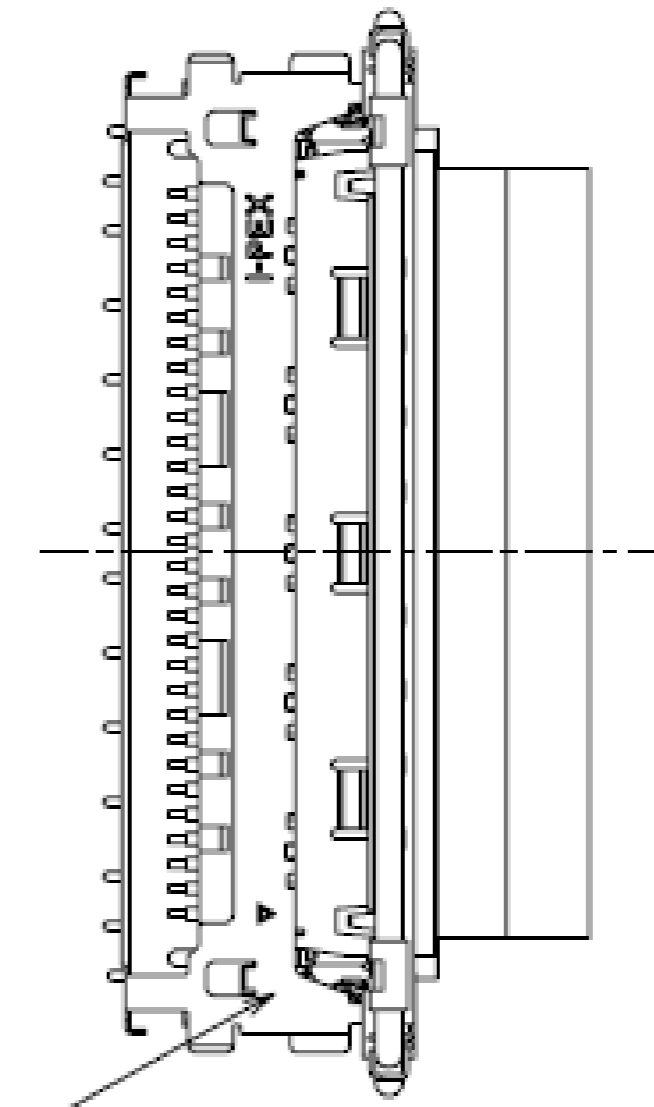
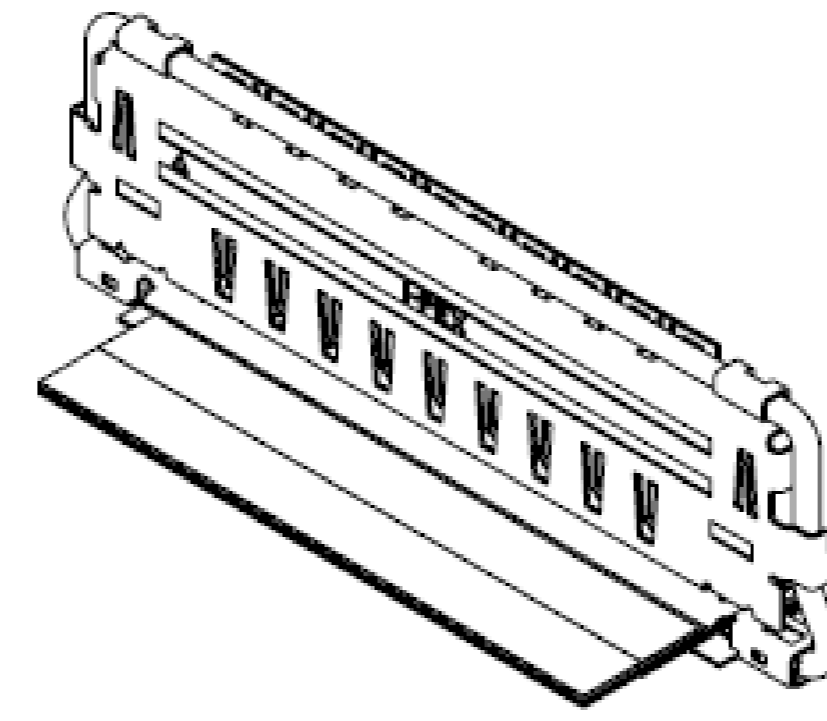
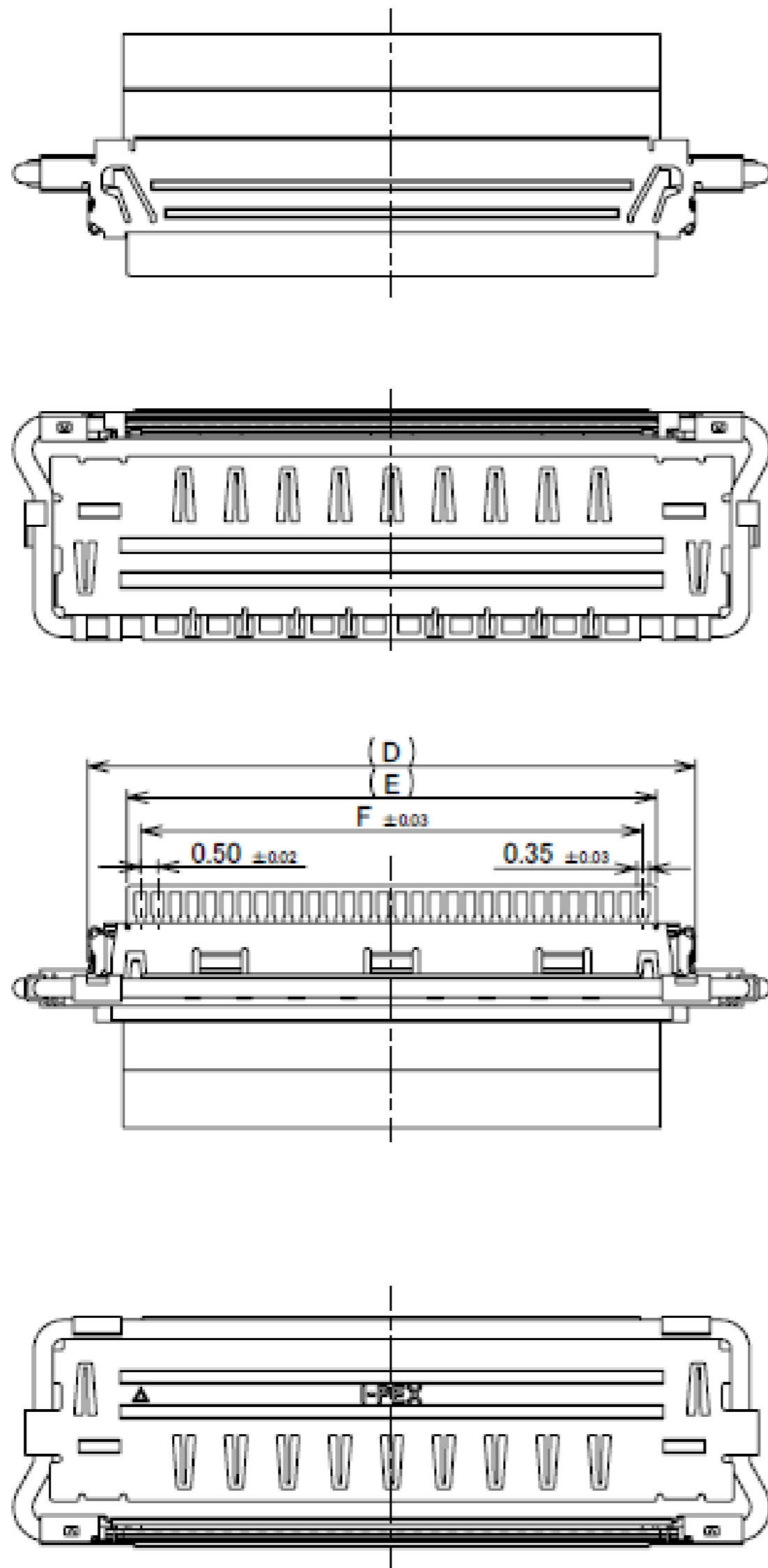
NOTES.
1.Soldering Area X is recommended dimension.
It does not mater if it might be exceed the recommended dimension.

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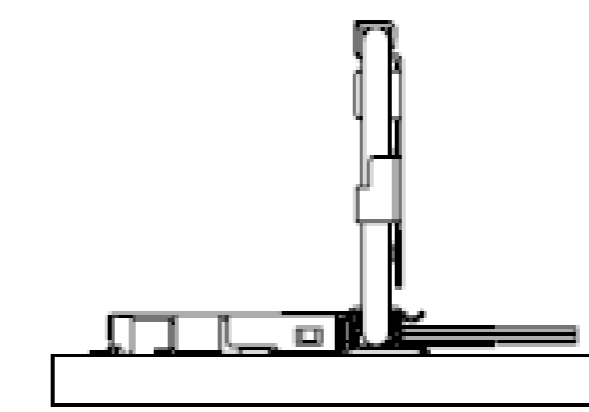
Shell Assembly

Recommended P/N		20862-0**T-01		
PART No.	Pos.	D	E	F
20862-030T-01	30	17.56	15.30	14.50
20862-040T-01	40	22.56	20.30	19.50

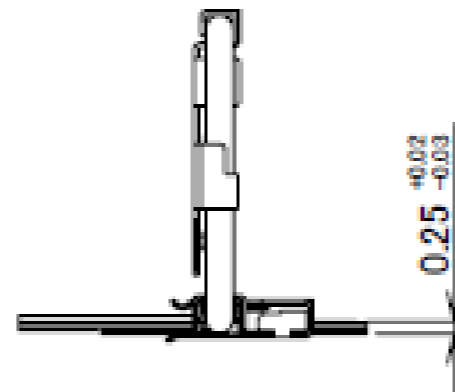
FPC ASS'Y STATE COVER OPEN



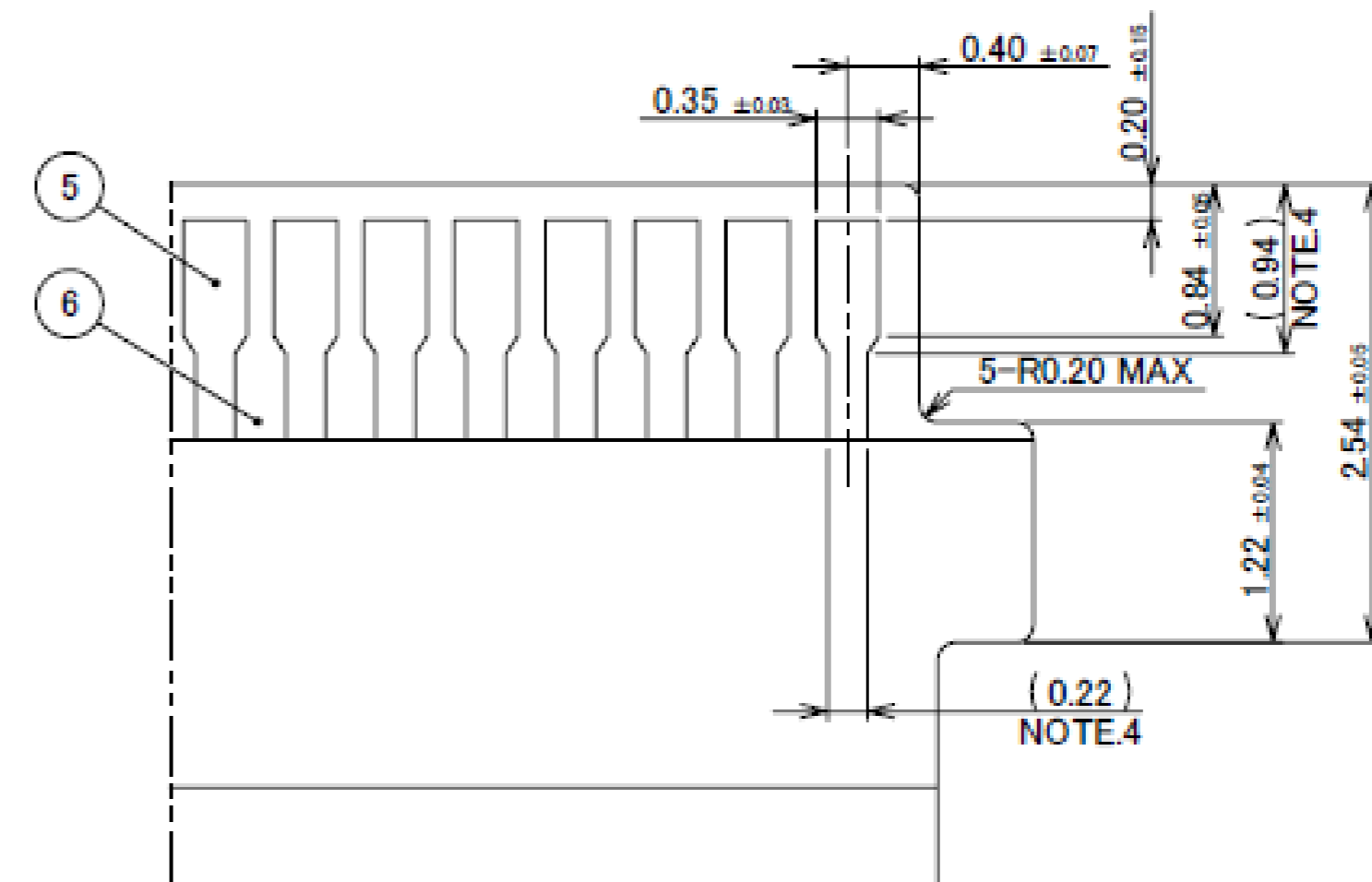
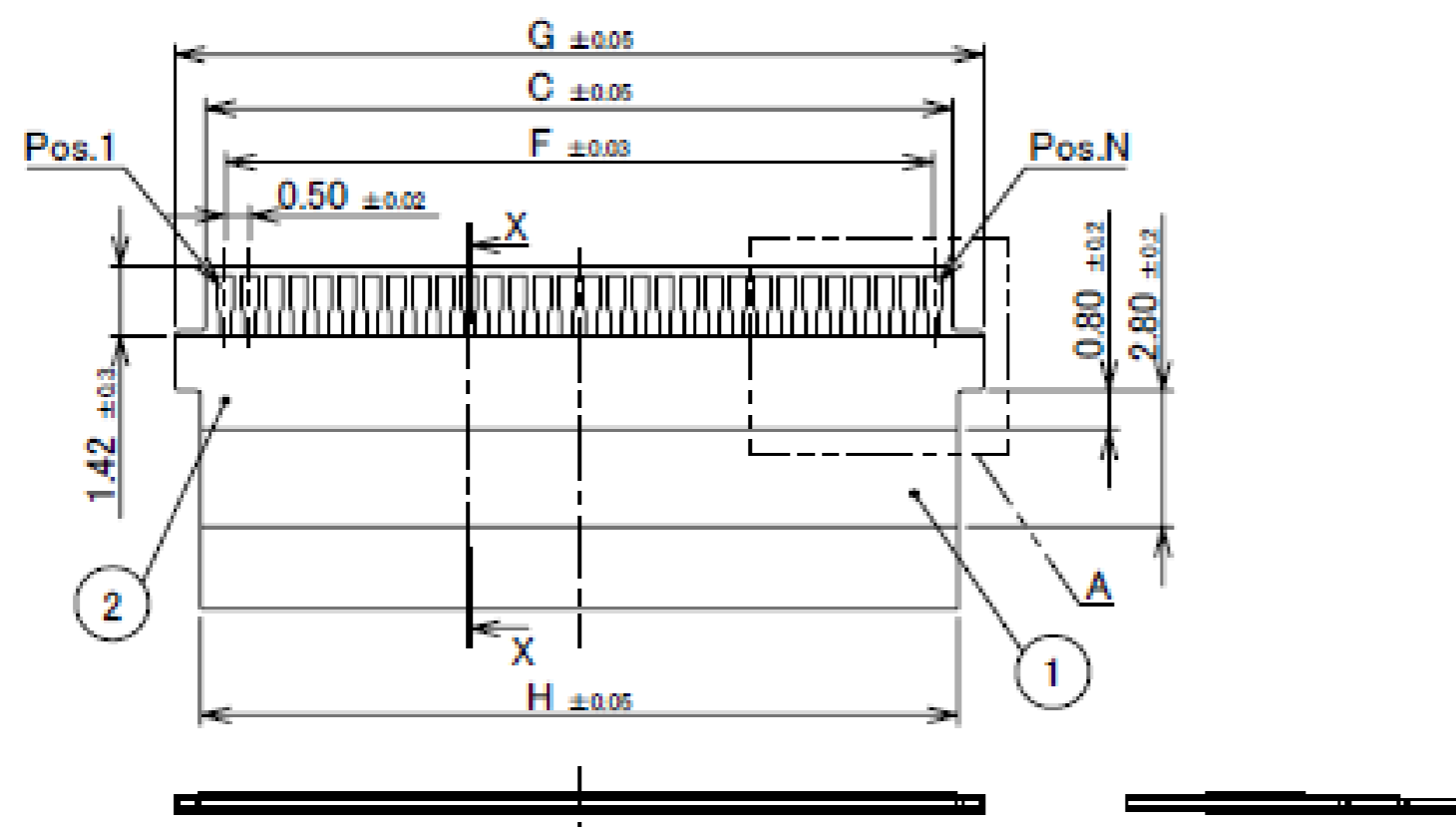
RECE ASS'Y (P/N:20849-0**E-01)



MATING CONDITION



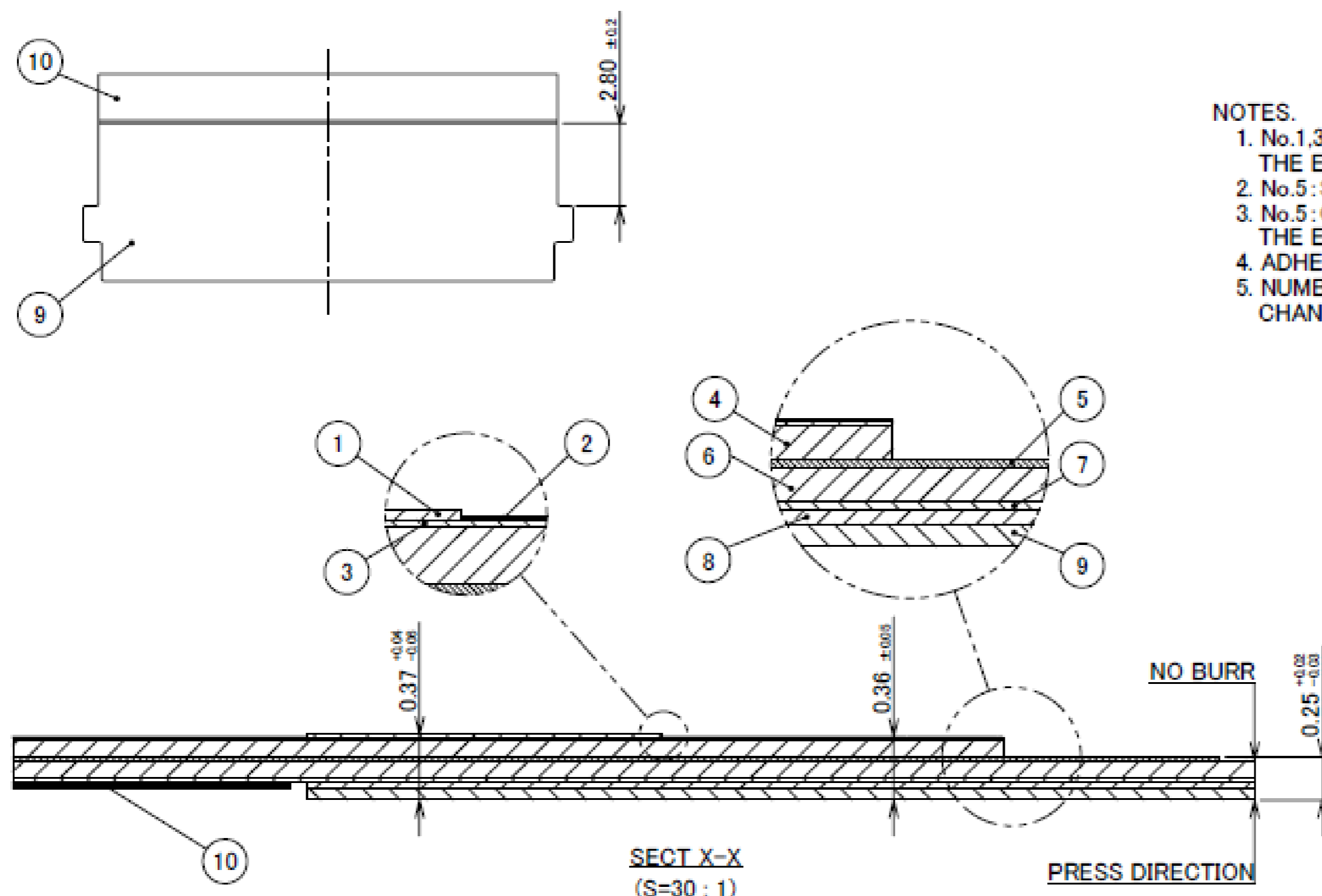
PART No.	Pos.	C	F	G	H
20862-030T-01	30	15.30	14.50	16.56	15.50
20862-040T-01	40	20.30	19.50	21.56	20.50



DETAIL A
(S=20/1)

NOTES.

- No.1,3,7,9: CONDUCTOR(GROUND) ARE CARRYING OUT THE ELECTRICAL CONNECTION.
- No.5: SIGNAL Pos. AND No.1,3,7,9: CONDUCTOR(GROUND) ARE NOT CONTACTING.
- No.5: GROUND Pos. AND No.1,3,7,9: CONDUCTOR(GROUND) ARE CARRYING OUT THE ELECTRICAL CONNECTION.
- ADHESIVE SHOULD USE THERMOSETTING.
- NUMBERS WITHIN PARENTHESES ARE ARBITRARY DIMENSIONS. CHANGE DIMENSIONS IN ACCORDANCE WITH CHARACTERISTIC IMPEDANCE VALUE.



SECT X-X
(S=30 : 1)

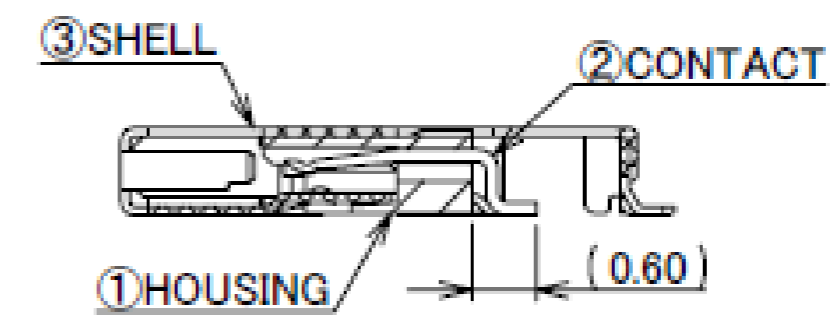
PRESS DIRECTION

No.	DESCRIPTION	MATERIAL	PLATING
1	CONDUCTOR(GROUND)	Cu	Ni , Au
2	INSULATOR	-	-
3	CONDUCTOR(GROUND)	Cu	-
4	INSULATOR	-	-
5	CONDUCTOR(SIGNAL,GROUND)	Cu	Ni , Au
6	INSULATOR	-	-
7	CONDUCTOR(GROUND)	Cu	-
8	CONDUCTIVE ADHESIVE	-	-
9	REINFORCING TAPE & CONDUCTOR(GROUND)	SUS	Ni
10	INSULATOR	-	-

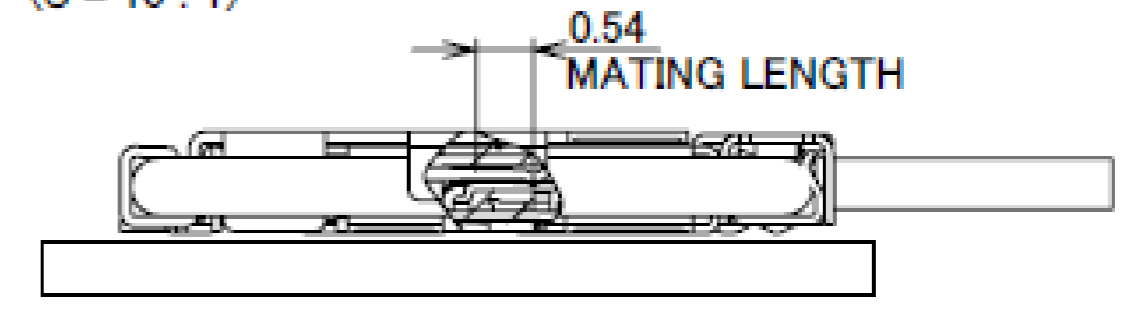
Receptacle Assembly

Recommended P/N		20849-0**E-01				
PART NO.	Pos.	A	B	C	D	E
20849-020E-0#	20	11.30	9.50	14.33	15.10	11.91
20849-030E-0#	30	16.30	14.50	19.33	20.10	16.91
20849-040E-0#	40	21.30	19.50	24.33	25.10	21.91

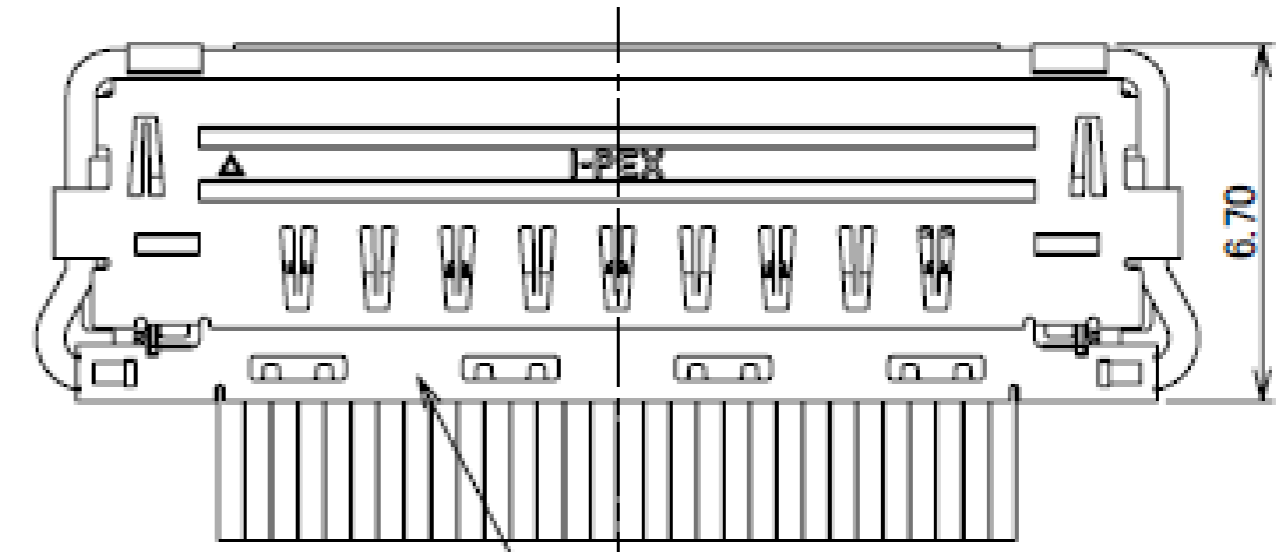
P/N : 20849-0**E-0#
SEE TABLE 1
POS.



SECT. W-W
(S = 10 : 1)



MATING CONDITION
(S = 10 : 1)



MATING CONDITION

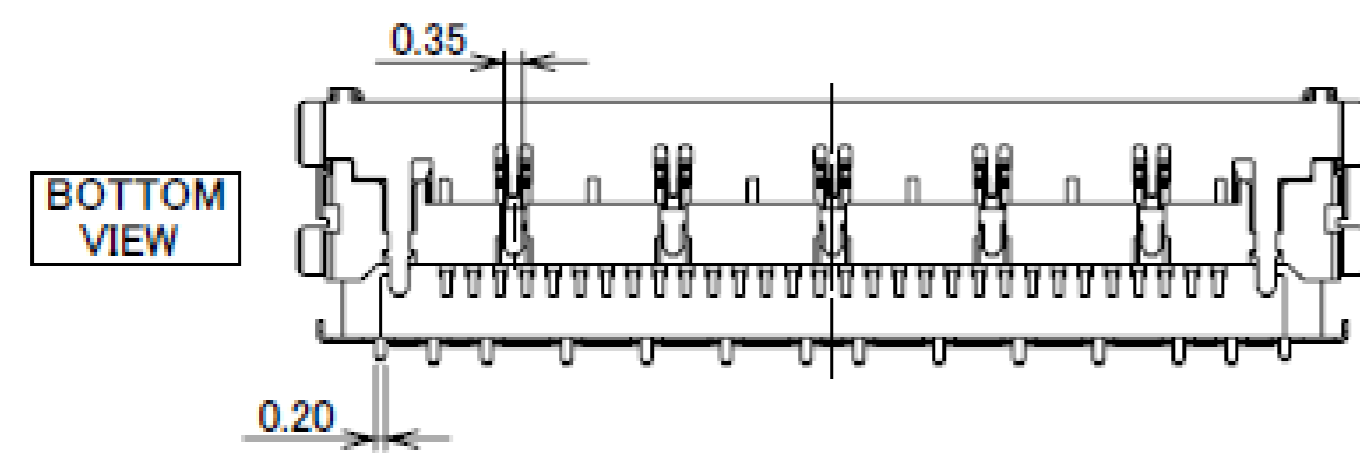
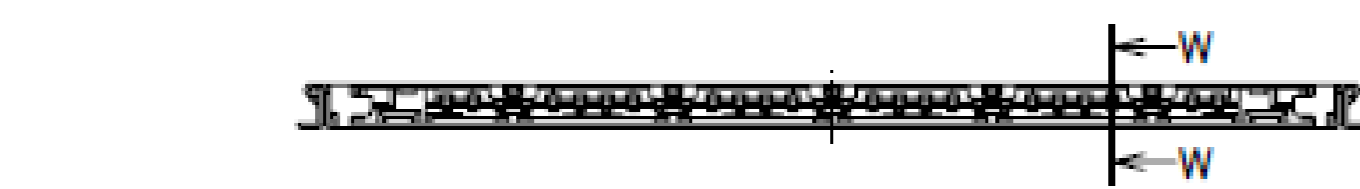
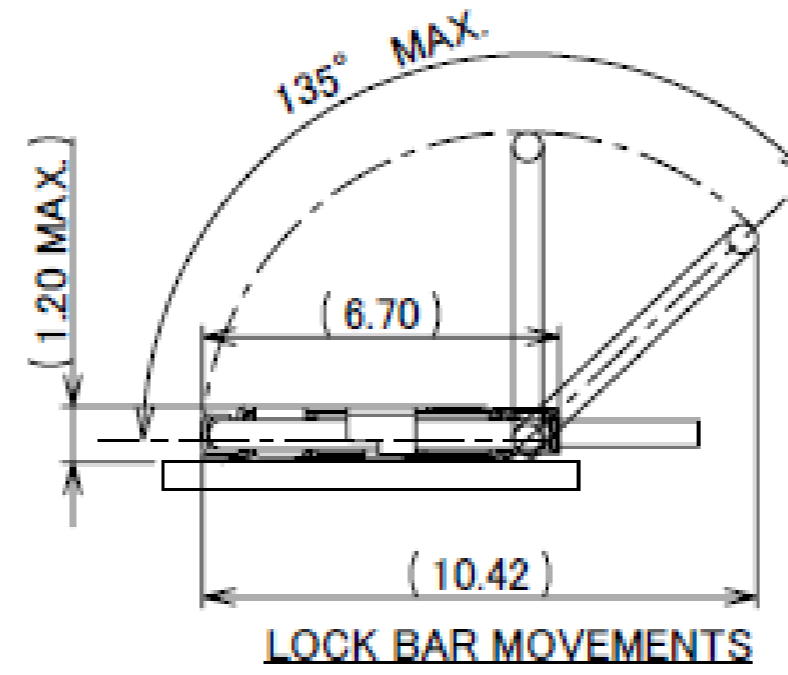
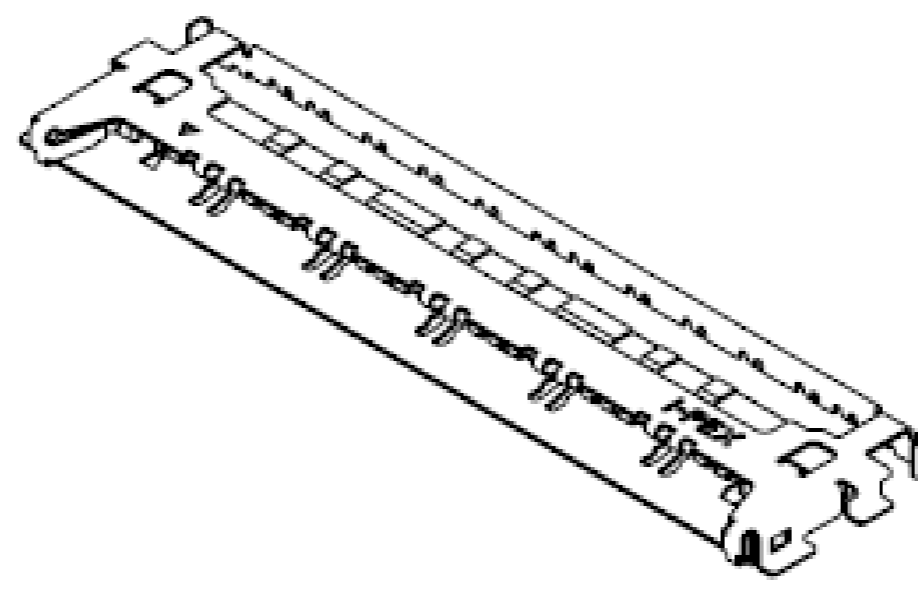
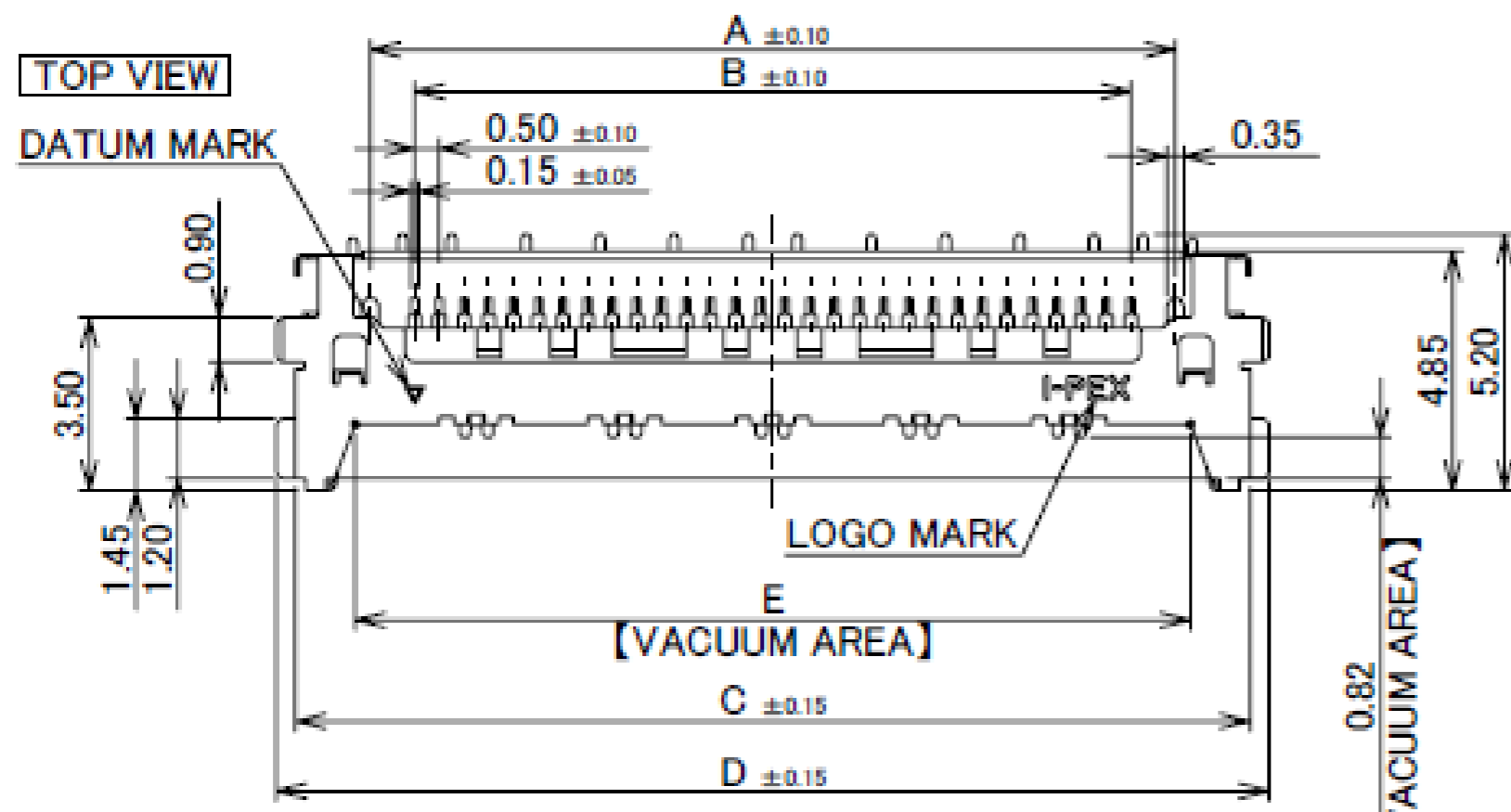
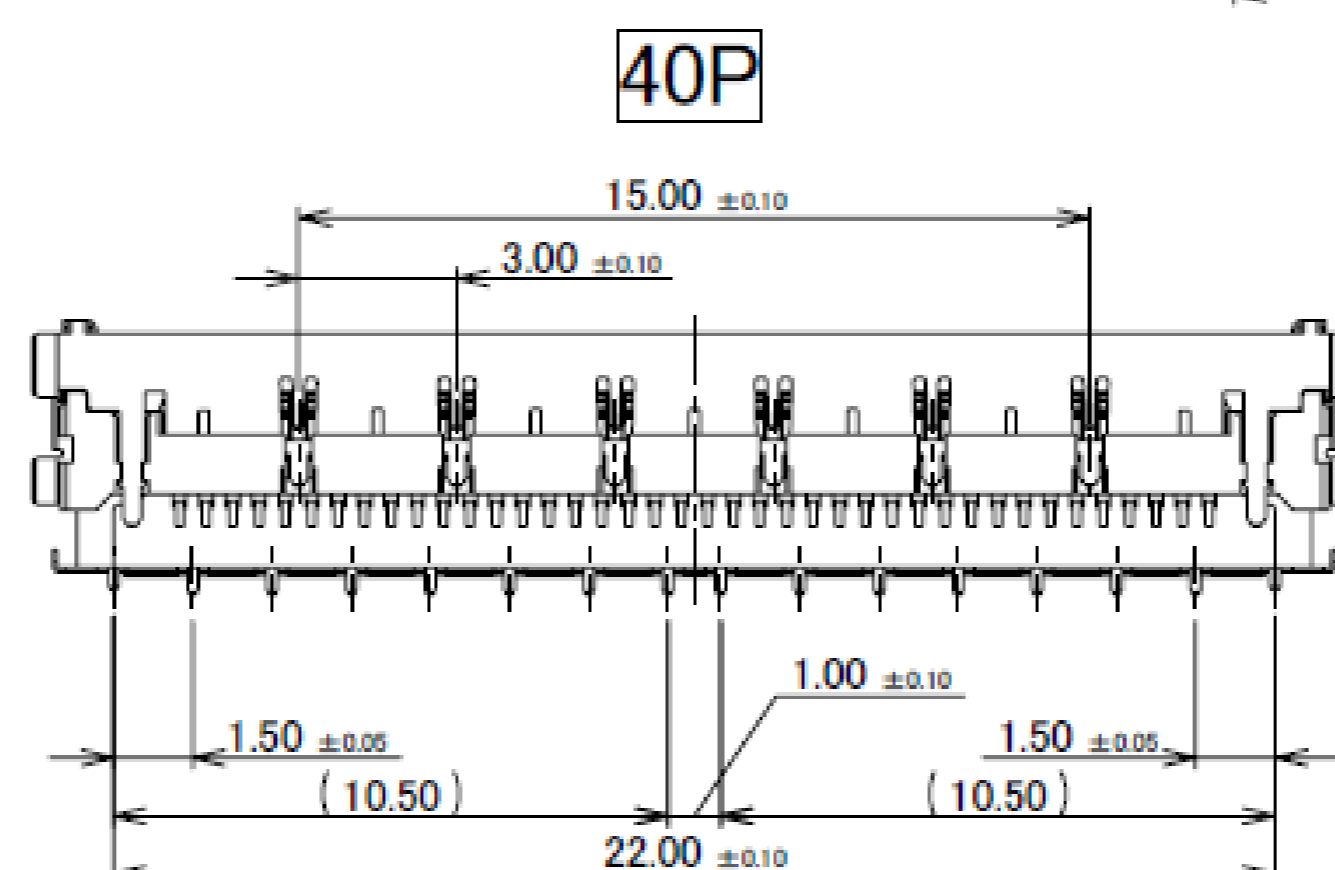
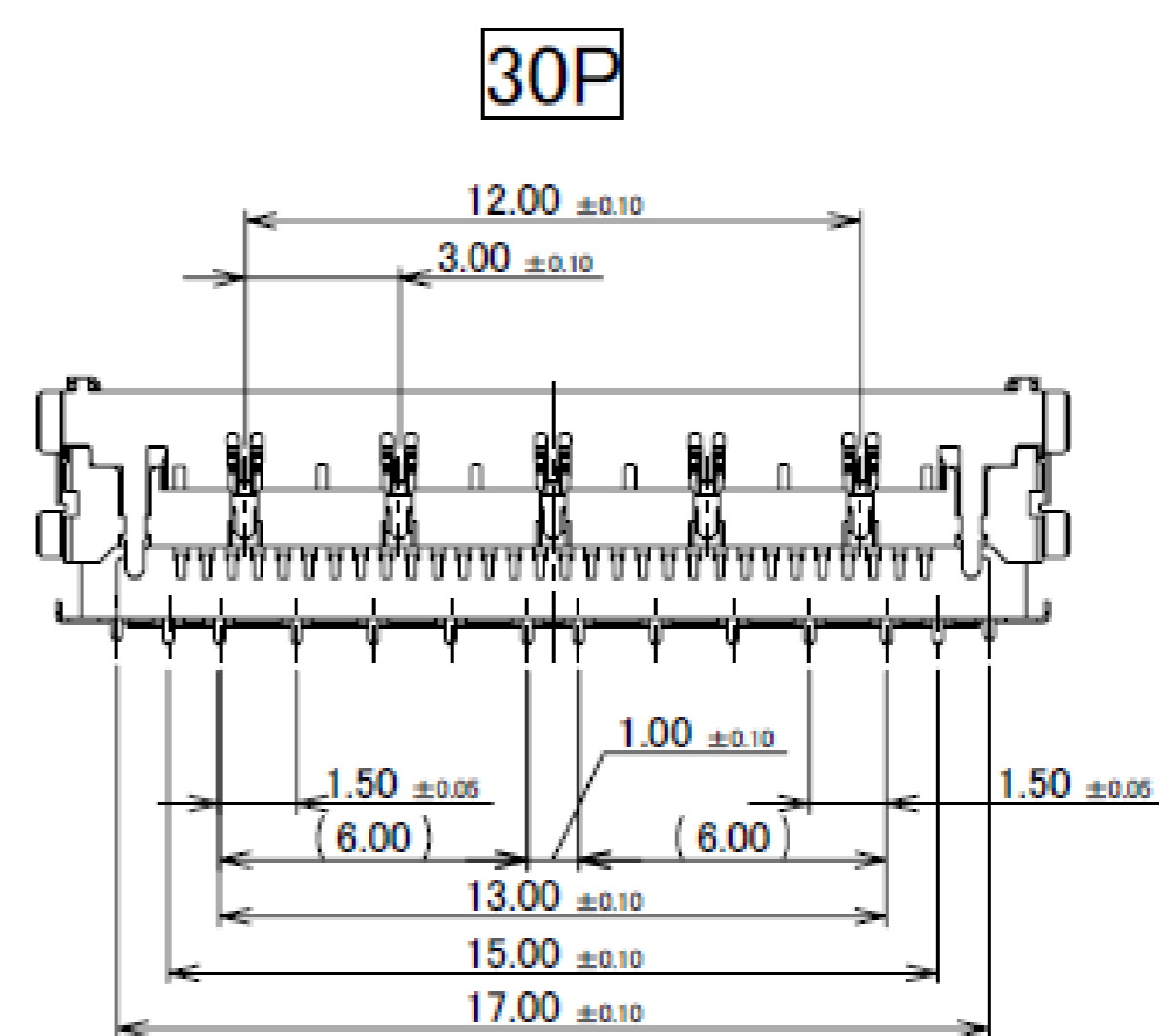
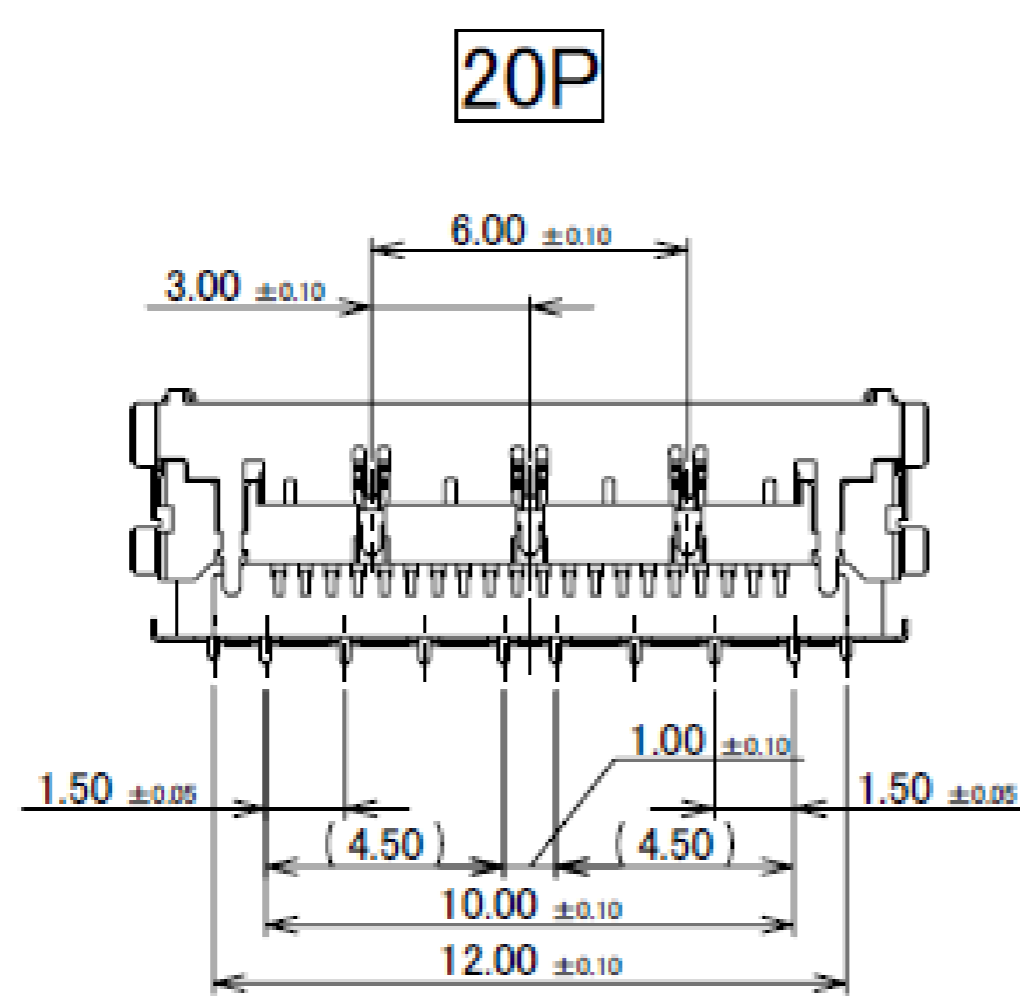


TABLE 1

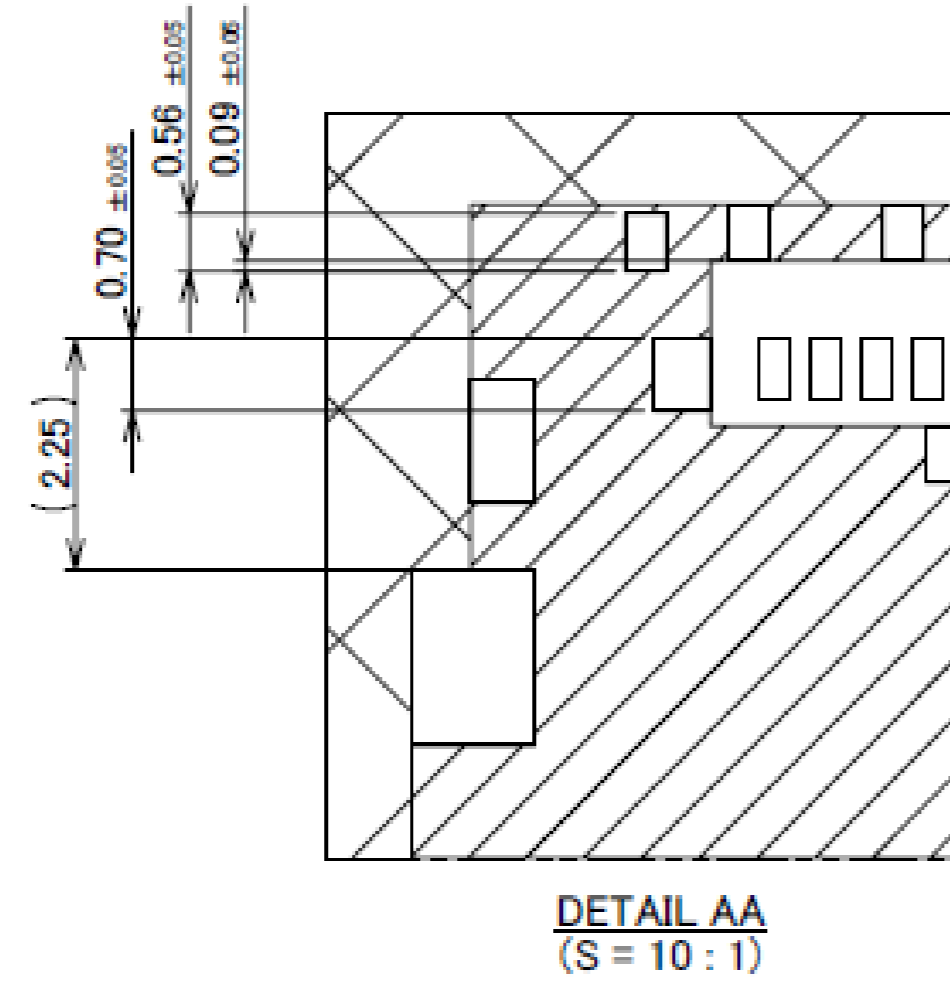
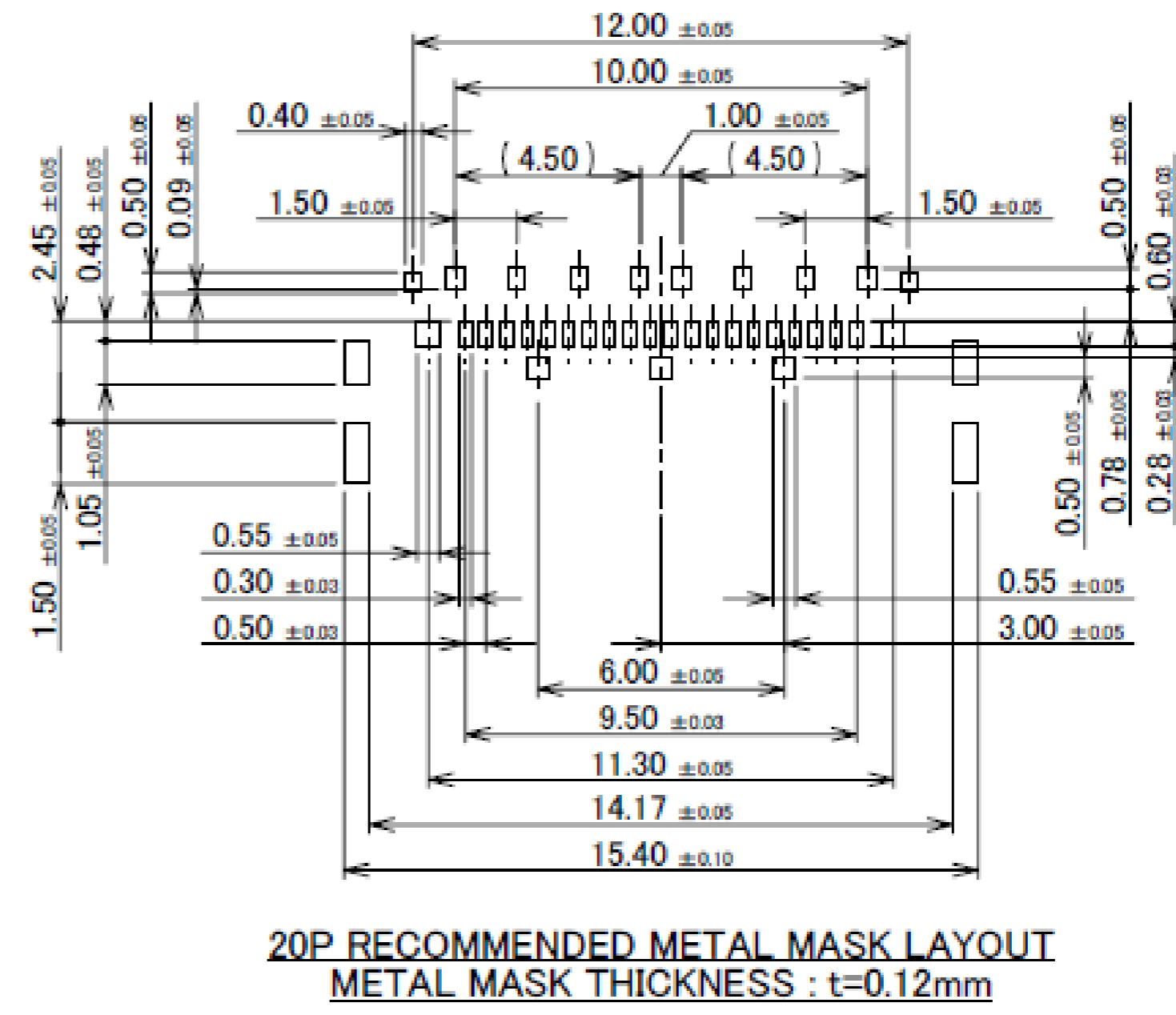
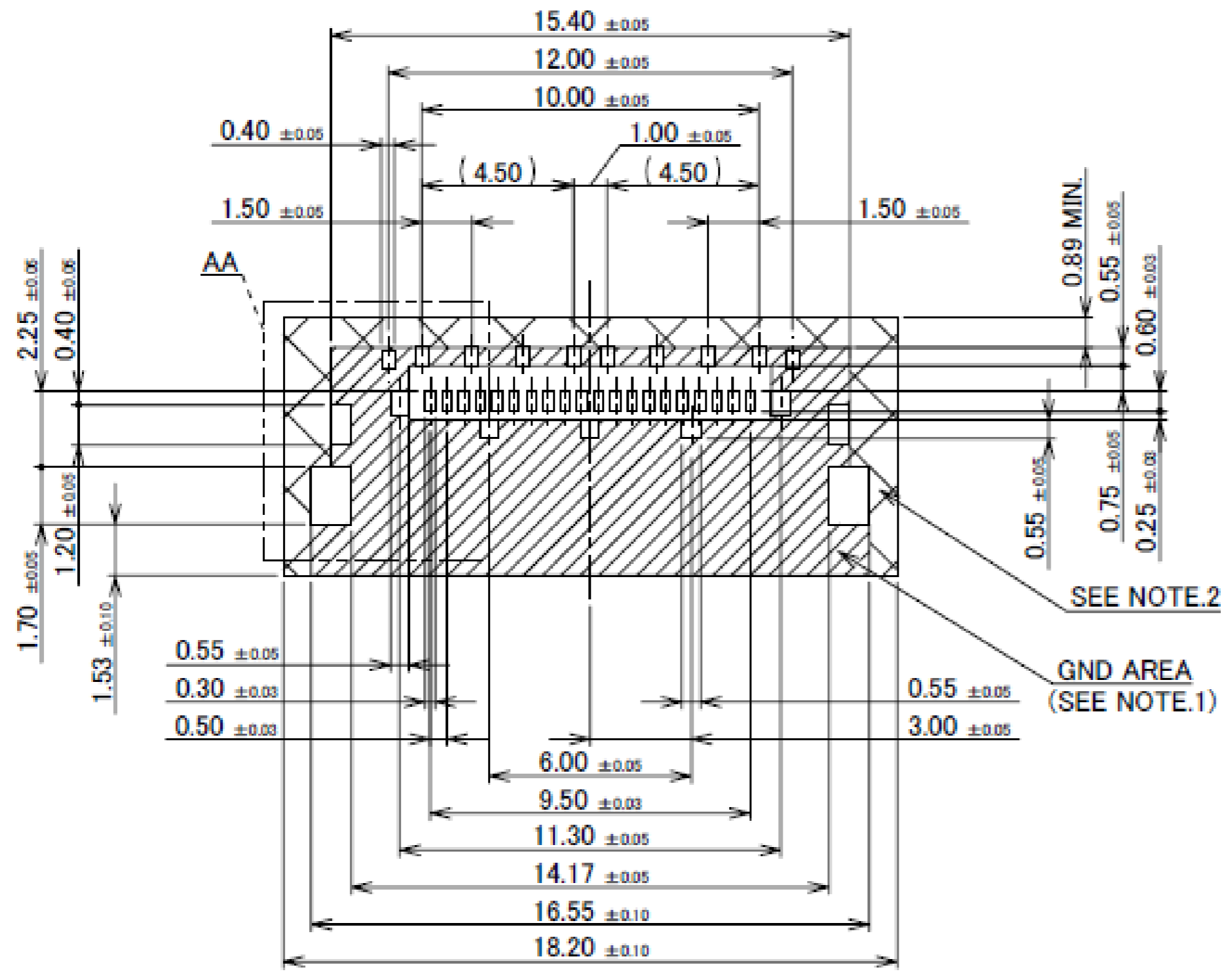
PART NO.	CONTACT FINISH	SHELL FINISH	
20849-0**E-01	CONTACT & SOLDERING AREA : Au 0.03 μm MIN. OVER Ni 1.00 μm MIN.	ALL OVER Ni 1.00 μm MIN. SOLDERING AREA : Au 0.02 μm MIN.	
20849-0**E-02	CONTACT AREA : Au 0.38 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING AREA : Au 0.03 μm MIN. OVER Ni 1.00 μm MIN.		
3 SHELL	PHOSPHOR BRONZE	SEE TABLE 1	
2 CONTACT	PHOSPHOR BRONZE	SEE TABLE 1	
1 HOUSING	LCP	UL94V-0, BLACK	
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

PART NO.	Pos.
20849-020E-0#	20
20849-030E-0#	30
20849-040E-0#	40

BOTTOM VIEW

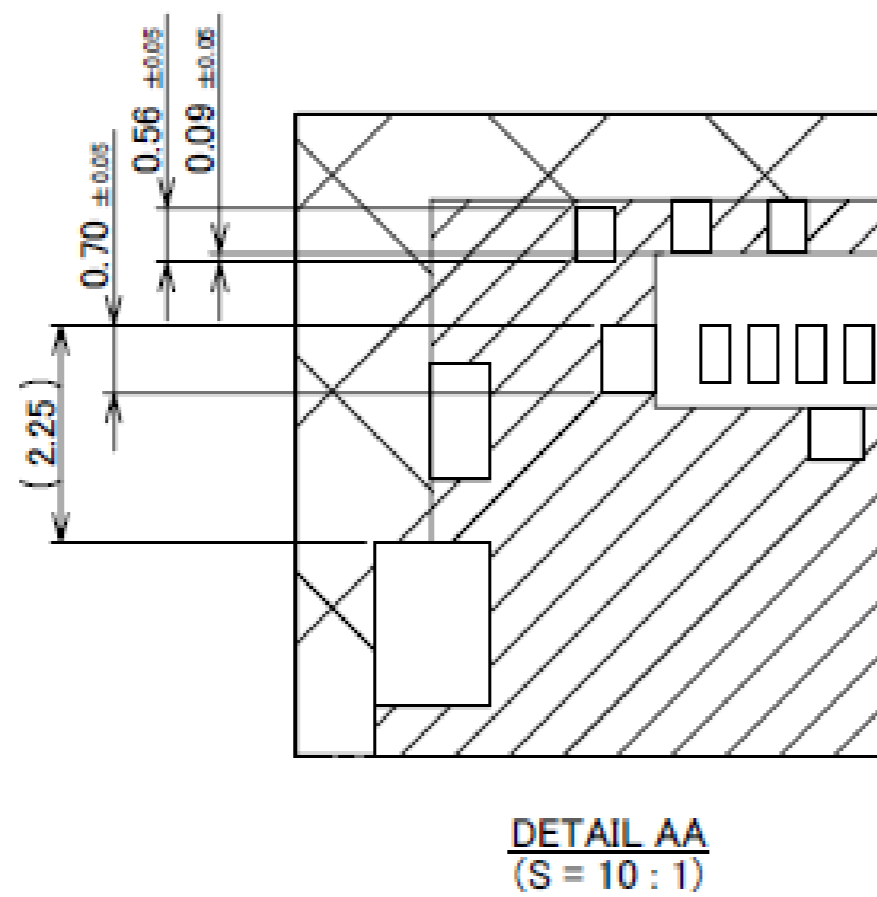
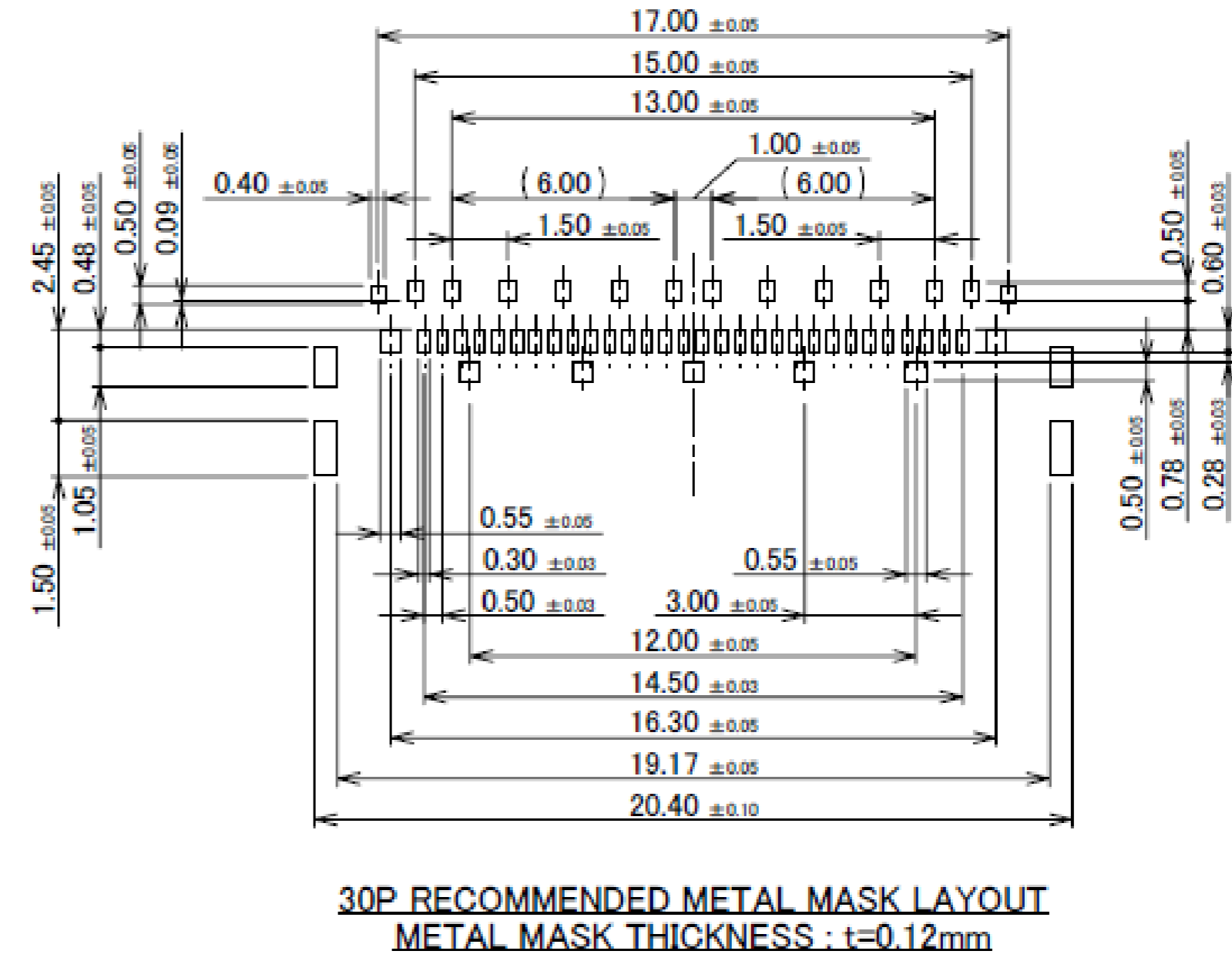
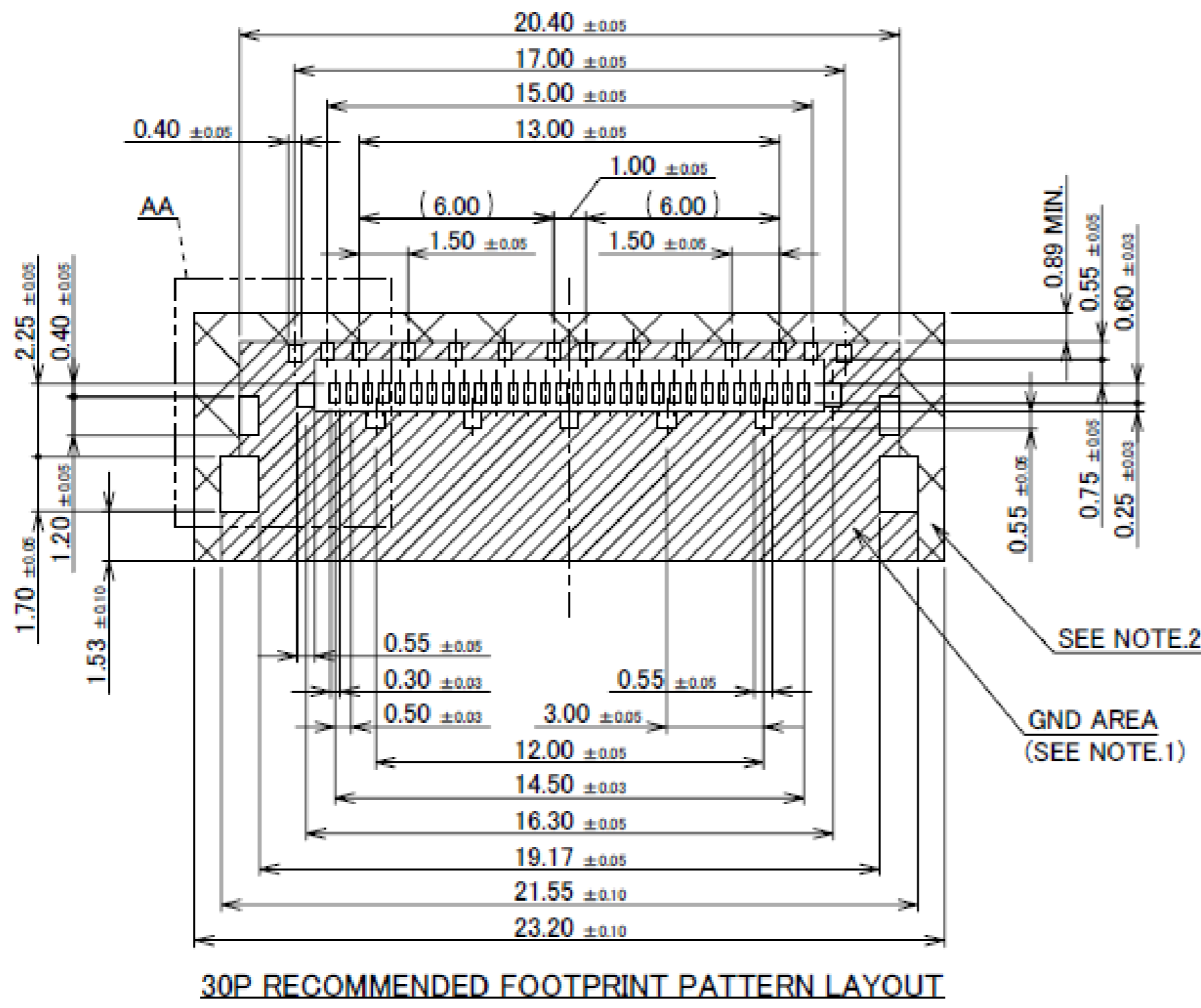


Receptacle Assembly



- NOTES.
1. SOLDER RESIST MUST BE APPLIED TO THIS AREA.
 2. DO NOT MOUNT ANOTHER COMPONENT IN THIS AREA.

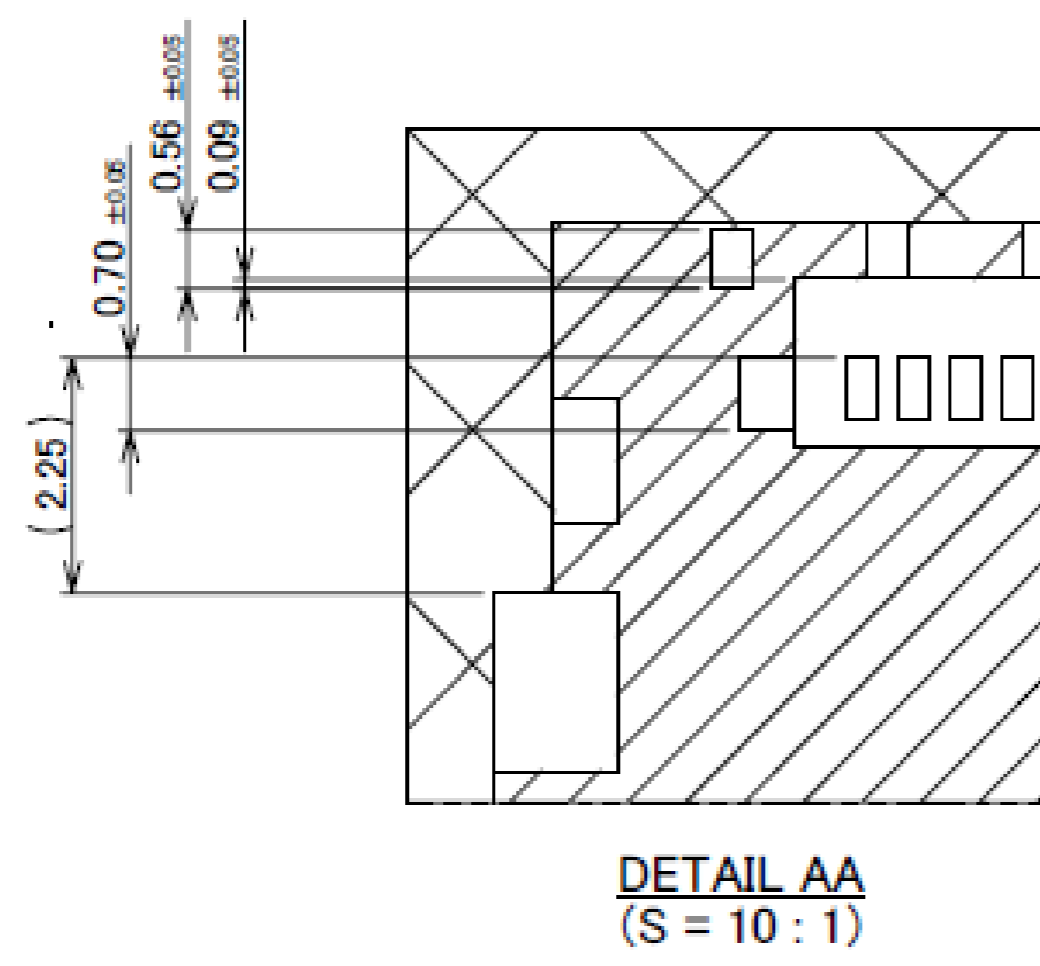
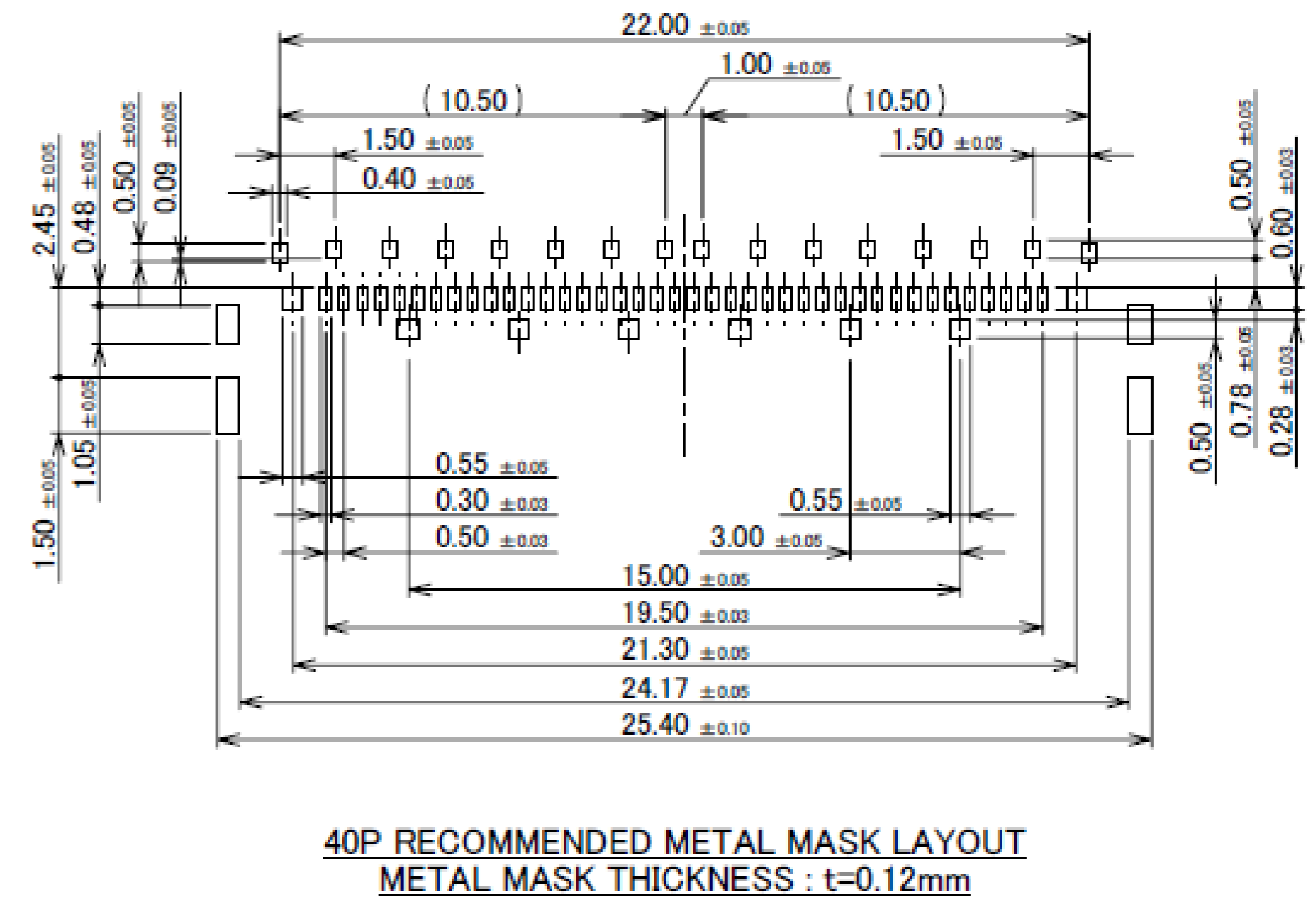
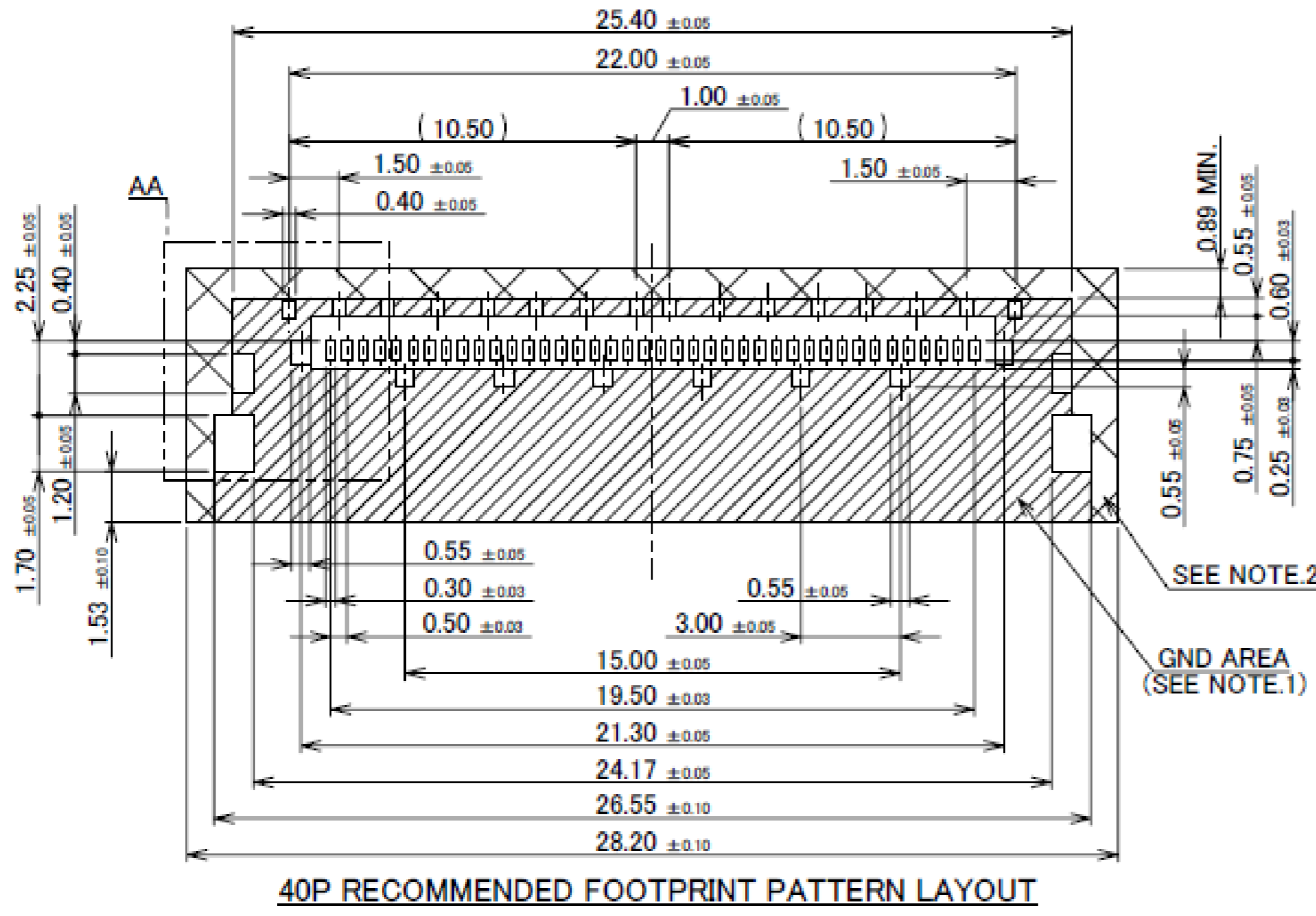
Rev.10



- NOTES.
1. SOLDER RESIST MUST BE APPLIED TO THIS AREA.
 2. DO NOT MOUNT ANOTHER COMPONENT IN THIS AREA.

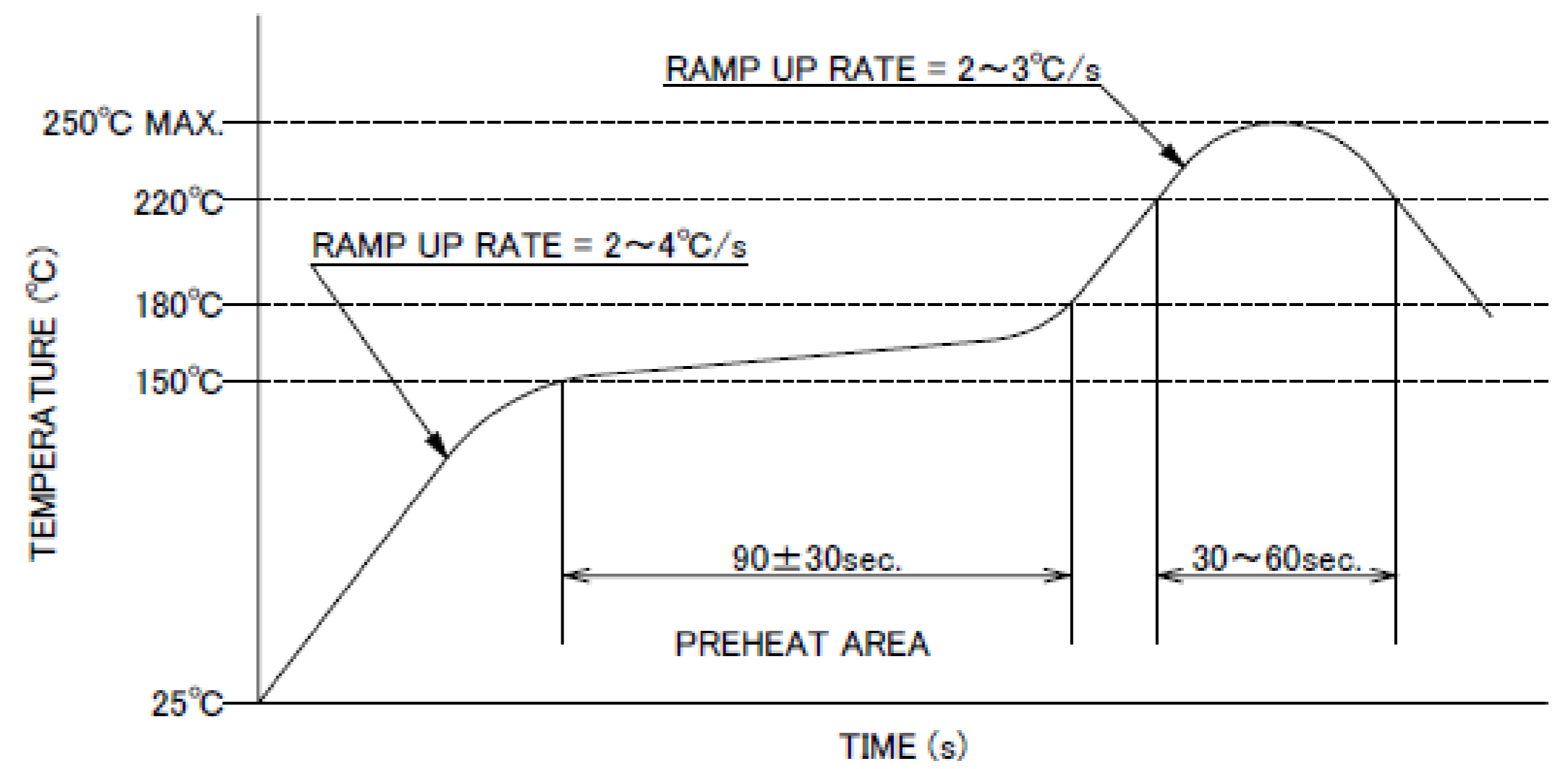
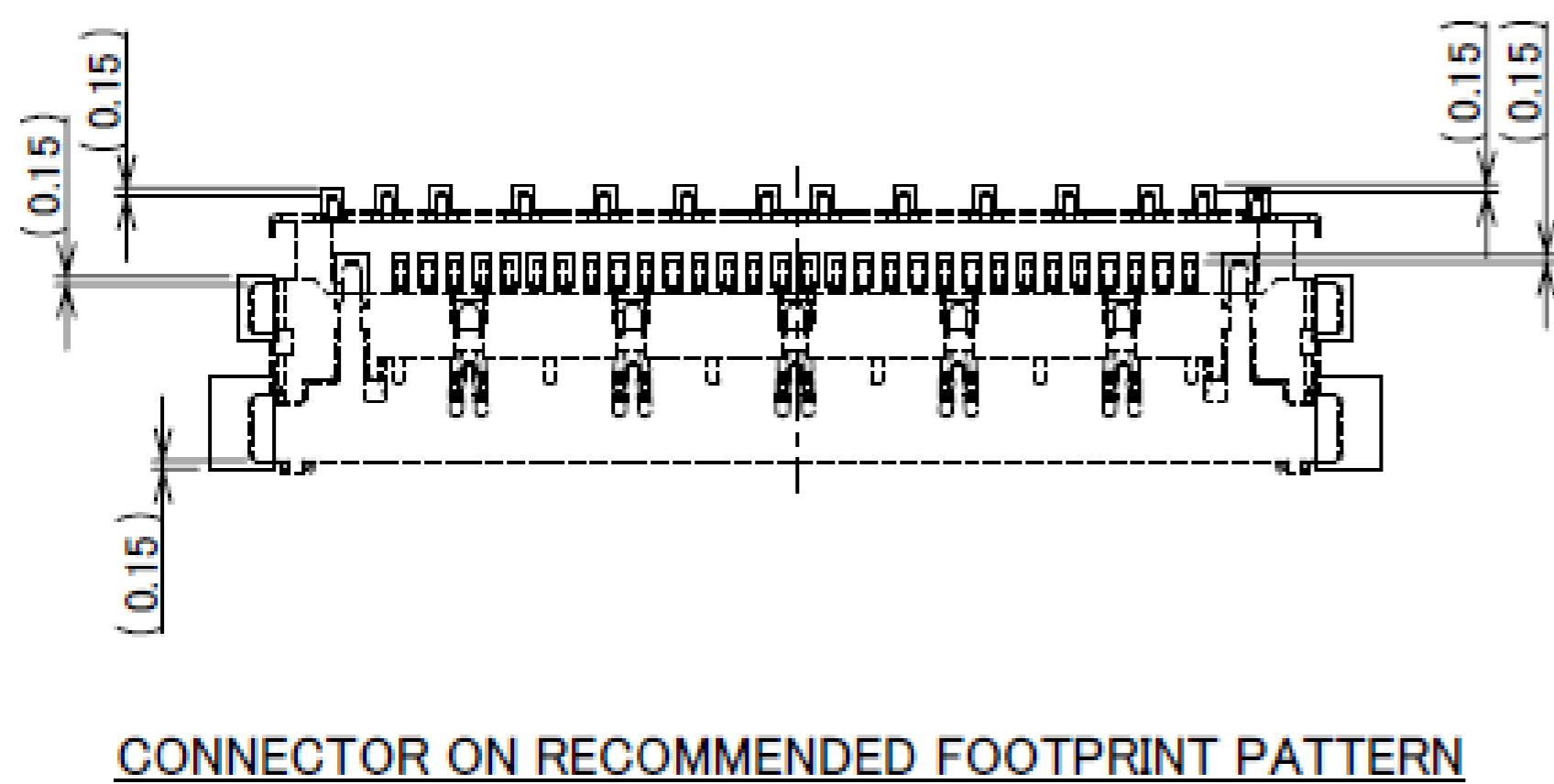
Rev.10

Receptacle Assembly



- NOTES.
 1. SOLDER RESIST MUST BE APPLIED TO THIS AREA.
 2. DO NOT MOUNT ANOTHER COMPONENT IN THIS AREA.

Rev.10



REFLOW TEMPERATURE PROFILE
 SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.10

ITEMS	SPECIFICATION
RATING VOLTAGE	100V AC (PER CONTACT PIN)
RATING AMPERAGE (FOR SIGNAL CONTACT)	0.3A AC/DC (PER CONTACT PIN)
OPERATING TEMPERATURE	233~358K(-40°C~+85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENSING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 60mohm MAX. / AFTER TEST : \triangle 40mohm MAX.
GROUND SHELL RESISTANCE	INITIAL : 60mohm MAX. / AFTER TEST : \triangle 40mohm MAX.
INSULATION RESISTANCE	INITIAL : 1000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	30 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	30P : 13.50N MAX. 40P : 18.00N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	30P : 1.44N MIN. 40P : 1.92N MIN.
PRODUCT SPECIFICATION	PRS-2430
TEST REPORT	TR-17086
PACKING STANDARD	PST-17134
INSTRUCTION MANUAL	HIM-17039
ASSEMBLY MANUAL	ASM-17010
APPEARANCE CRITERIA No.	QLS-A***

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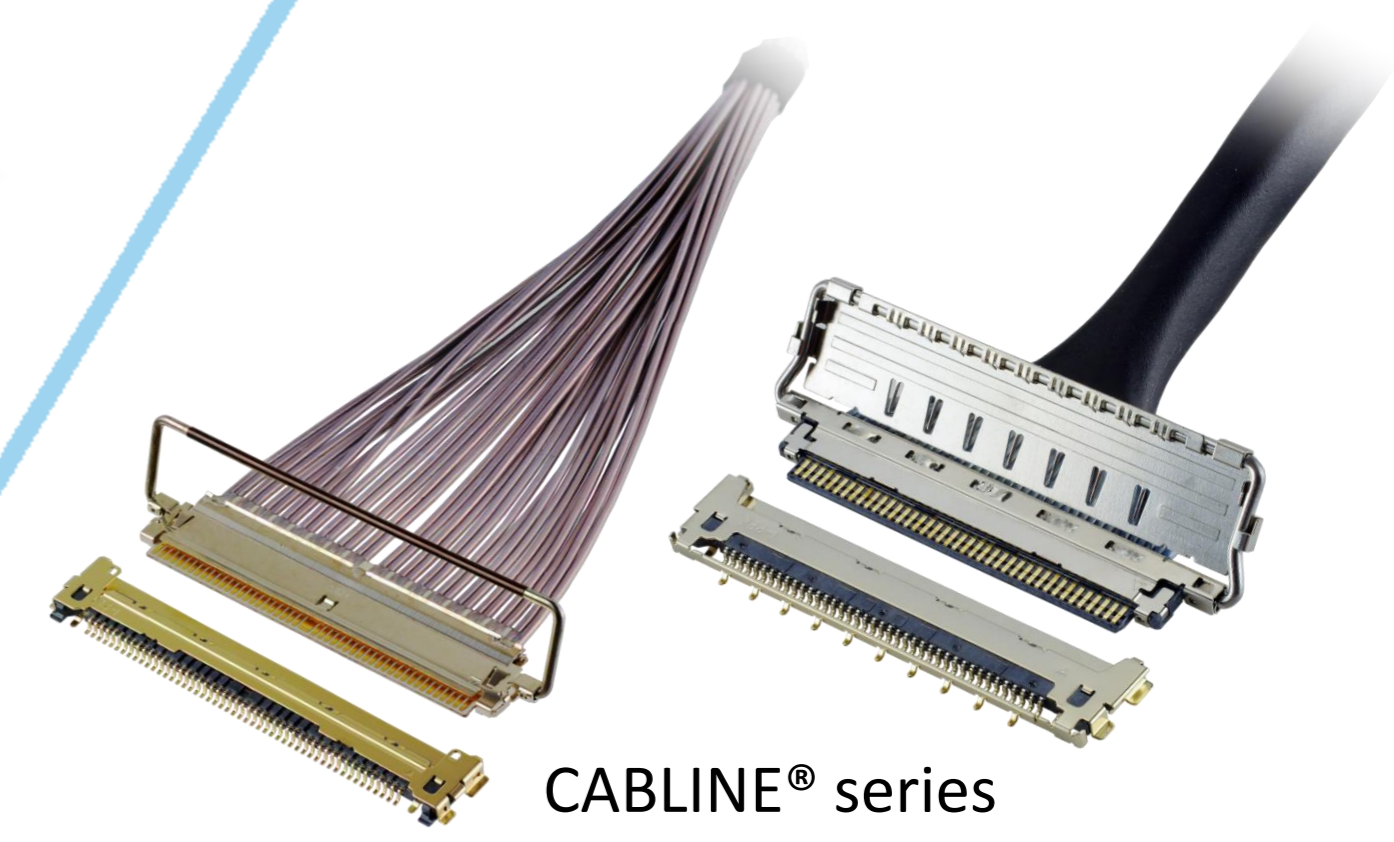
Custom Connectors Available

 RF Connector

MHF® series



CABLINÉ® series
Micro-coaxial/Twinax/
Discrete Wire Connector



Optical Module

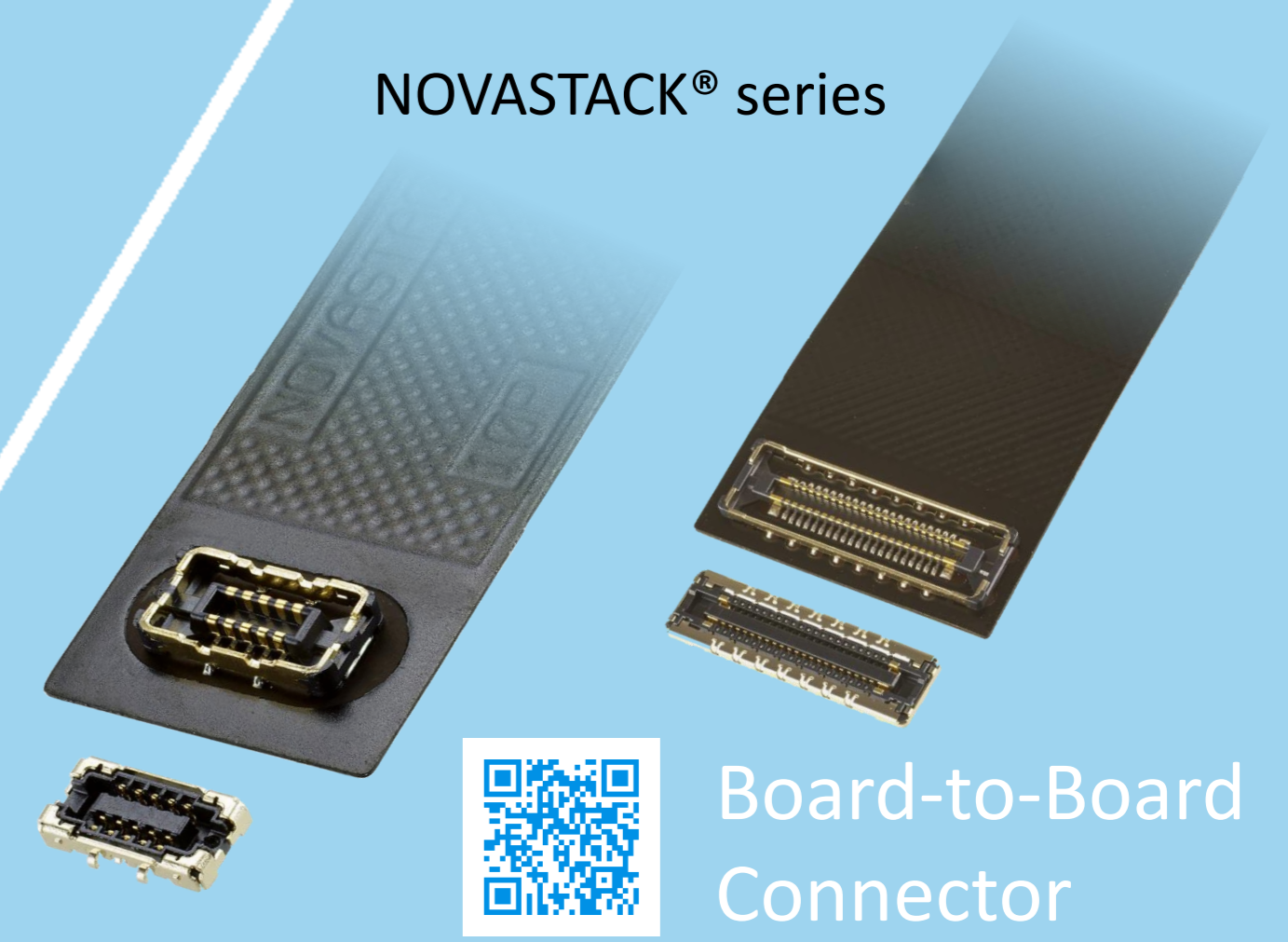
LIGHTPASS® series



NOVASTACK® series



Board-to-Board Connector



Power Connector/
Terminal

AP series

ISH® series



MINIFLEX® series

EVAFLEX® series



FPC FFC Connector



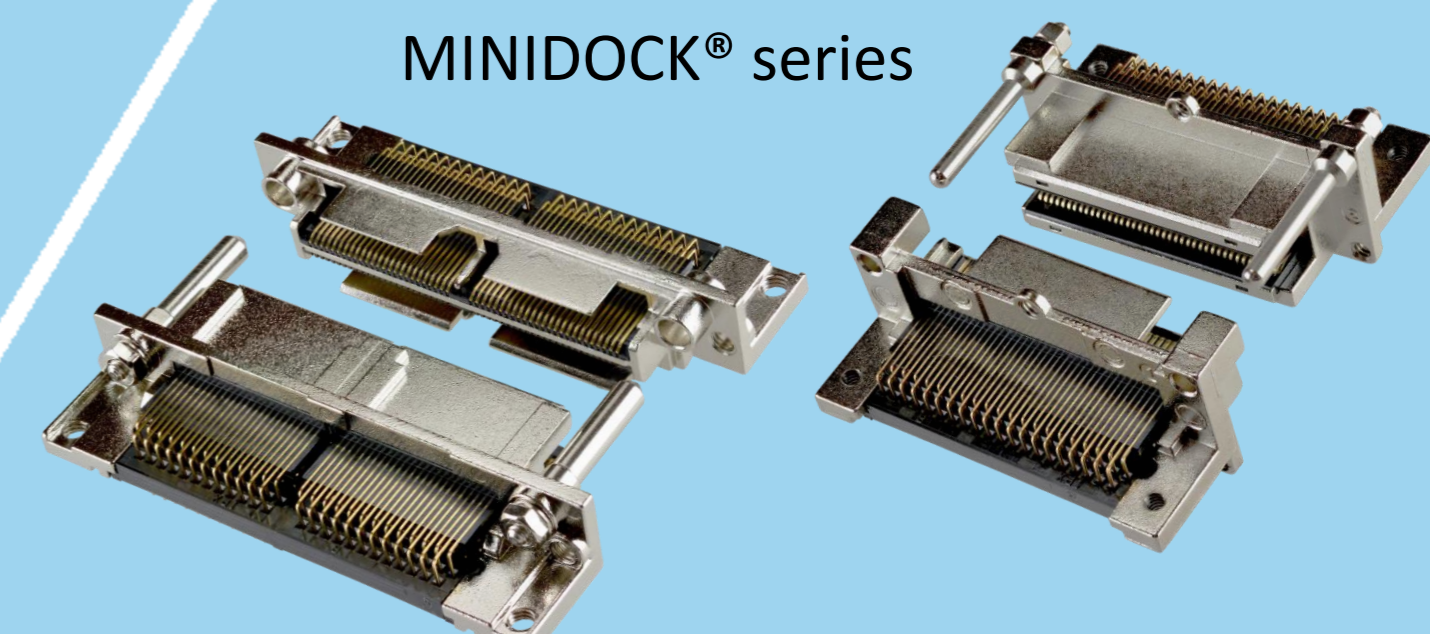
Inquiry



MINIDOCK® series



I/O Connector



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Contact your sales representative or more detailed information.

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